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Linux Interface Specification Yocto recipe Start-Up Guide

User's Manual: Software

R-Car H3/M3/M3N/E3 Series

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How to Use This Manual

- **[Readers]**

This manual is intended for engineers who develop products which use the R-Car H3/M3/M3N/E3 processor.

- **[Purpose]**

This manual is intended to give users an understanding of the functions of the R-Car H3/M3/M3N/E3 processor device driver and to serve as a reference for developing hardware and software for systems that use this driver.

- **[How to Read This Manual]**

It is assumed that the readers of this manual have general knowledge in the fields of electrical

— engineering, logic circuits, microcontrollers, and Linux.

→ Read this manual in the order of the CONTENTS.

— To understand the functions of a multimedia processor for R-Car H3/M3/M3N/E3

→ See the R-Car H3/M3/M3N/E3 User's Manual.

— To know the electrical specifications of the multimedia processor for R-Car H3/M3/M3N/E3

→ See the R-Car H3/M3/M3N/E3 Data Sheet.

- **[Conventions]**

The following symbols are used in this manual.

Data significance: Higher digits on the left and lower digits on the right

Note: Footnote for item marked with Note in the text

Caution: Information requiring particular attention

Remark: Supplementary information

Numeric representation: Binary ... xxxx, 0bxxxx, or xxxxB

Decimal ... xxxx

Hexadecimal ... 0xxxxx or xxxxH

Data type: Double word ... 64 bits

Word ... 32 bits

Half word ... 16 bits

Byte ... 8 bits

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Introduction

This start-up guide explains R-Car H3/M3/M3N/E3 Yocto recipe package files, the system environments, the make method of kernel, the operating of U-Boot and so on.

This product R-Car H3/M3/M3N/E3 Yocto recipe is a basic package to operate built-in Linux and basic middleware on the R-Car H3/M3/E3 System Evaluation Board. Please contact Renesas Electronics person who provided this product to you in case of questions.

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1. R-Car H3/M3/M3N/E3 Linux BSP package files

This Yocto recipe will be taken

The U-Boot source code from:

[git://github.com/renesas-rcar/u-boot.git](https://github.com/renesas-rcar/u-boot.git)

R-Car H3/M3/M3N/E3 Linux source code from:

<https://github.com/renesas-rcar/linux-bsp.git>

1.1 Reference (R-Car H3/M3/M3N/E3)

Document name	Version
R-Car Series, 3rd Generation User's Manual: Hardware	Rev.1.50
R-CarH3-SiP System Evaluation Board Salvator-X Hardware Manual RTP0RC7795SIPB0011S	Rev.1.09
R-CarM3-SiP System Evaluation Board Salvator-X Hardware Manual RTP0RC7796SIPB0011S	Rev.0.04
R-CarH3-SiP/M3-SiP/M3N-SiP System Evaluation Board Salvator-XS Hardware Manual	Rev.2.04
R-CarE3 System Evaluation Board Ebisu Hardware Manual RTP0RC77990SEB0010S	Rev.0.03
R-CarE3 System Evaluation Board Ebisu-4D (E3 board 4xDRAM) Hardware Manual	Rev.1.01
R-CarH3-SiP/M3-SiP/M3N-SiP System Evaluation Board Salvator-XS Setup Manual	Rev.2.04

2. Environmental Requirement

2.1 Setting of parts

Host PC and terminal software are necessary for the operation of this product. Furthermore, Ethernet cable is required to use NFS mount function. Please refer to Table 1.

Table 1 R-Car H3/M3/M3N/E3 Linux BSP Environmental Requirement

Equipment	Explanation
Linux Host PC	Ubuntu 16.04 LTS (64bit) is recommended as OS. 32bit version is not supported. It is used as building and debugging environment. It is used as TFTP server and NFS server.
Windows Host PC	Windows 10 is recommended as OS. It is used as debugging environment. Terminal software and VCP driver are executed.
Terminal software	Please use following software. 1) Tera Term (Confirmed with Japanese version of Tera Term 4.88 Available at http://sourceforge.jp/projects/ttssh2)
VCP driver	Please install in Windows Host PC. Execute CP210xVCPInstaller_x86/x64.exe for install before connect. USB become virtual COM port on terminal software. Please connect to CN25 (Serial-USB Bridge CP2102) on H3/M3/E3 System Evaluation Board. (Available at http://www.silabs.com/products/mcu/Pages/USBtoUARTBridgeVCPDrivers.aspx)
TFTP server software	It is used when Hyper Flash is written by U-Boot or Image is downloaded.
NFS server software	It is used when File system is mounted by NFS.

Recommended Environment

The following shows a Recommended Environment.

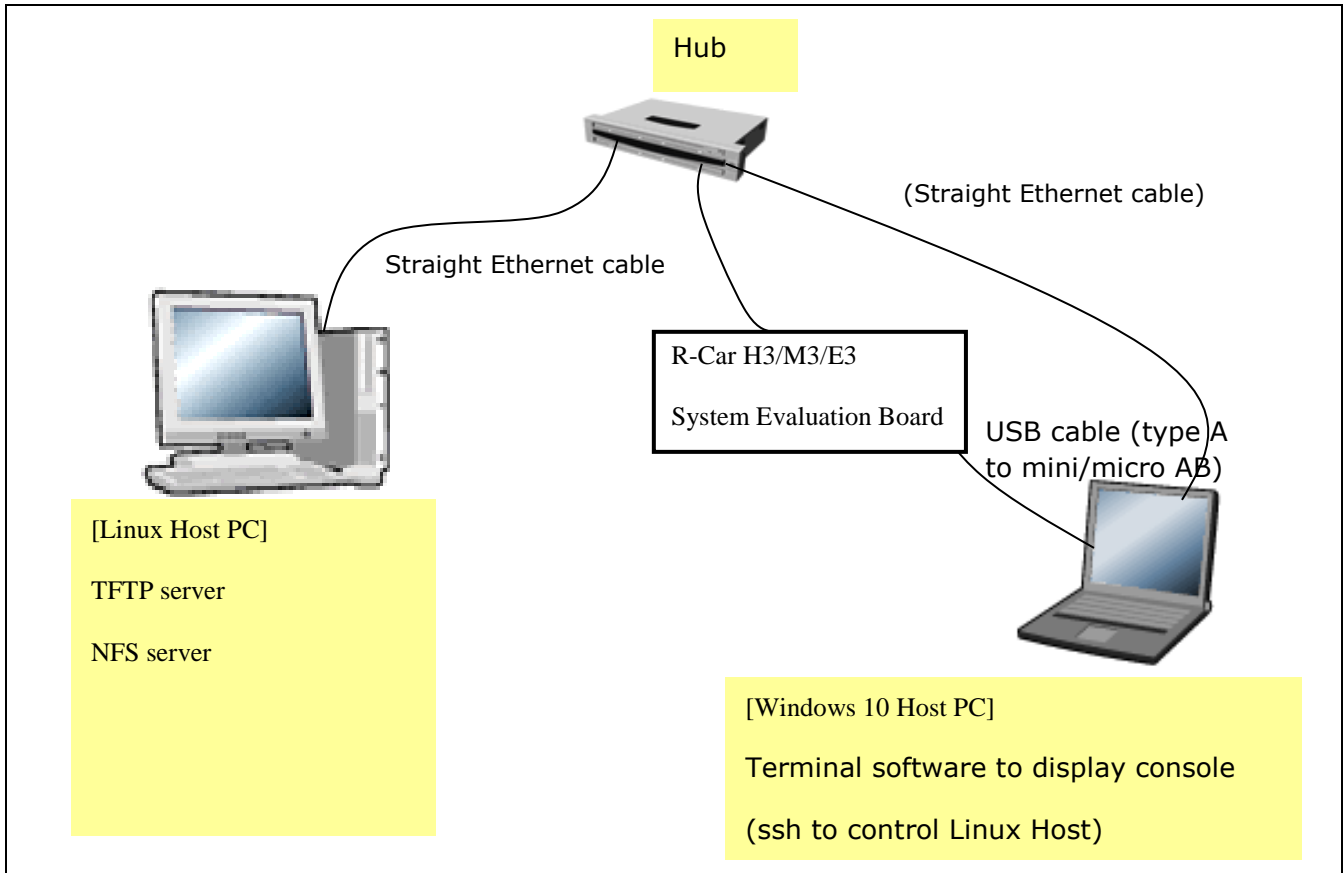


Figure 1. Recommended Environment for R-Car H3/M3/M3N/E3 Linux BSP

Note) Functions in covered with () are optional.

2.2 Setting of dip switch

The setting of R-Car H3/M3/E3 System Evaluation Board's dip switches is shown in the following Table 2, Table 3.

For Salvator-X board, please refer to “R-CarH3-SiP System Evaluation Board RTP0RC7795SIPB0011S (Salvator-X) Hardware Manual”.

For Salvator-XS board, please refer to “R-CarH3-SiP/M3-SiP/M3N-SiP System Evaluation Board RTP0RC7795SIPB0012S (Salvator-XS) Setup Manual”.

For Ebisu board, please refer to “R-CarE3 System Evaluation Board RTP0RC77990SEB0010S (Ebisu) Setup Manual”.

For Ebisu-4D board, please refer to “R-CarE3 System Evaluation Board RTP0RC77990SEB0020S Ebisu 4xDRAM (Ebisu-4D) Setup Manual”.

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Table 2 setting of Dip switches (R-Car H3 Ver.3.0, 2.0, M3 Ver.1.x, Ver.3.0, M3N Ver.1.1)

Switch Number	Switch Name	Side (C/S)	Pin1	Pin2	Pin3	Pin4	Pin5	Pin6	Pin7	Pin8
SW1	QSPI-A	S	OFF	OFF	OFF	OFF	OFF	OFF	-	-
SW2	QSPI-B	S	OFF	OFF	OFF	OFF	OFF	OFF	-	-
SW3	QSPI-C	S		✓ (ON)	-	-	-	-	-	-
SW13	QSPI-D	C	✓	-		-	-	-	-	-
SW4	SOFTSW	C	OFF	OFF	OFF	OFF	-	-	-	-
SW5	GPIO/PWM1	S			✓	-	-	-	-	-
SW6	GPIO/PWM2	S		✓		-	-	-	-	-
SW7	DDRBKUP-A	S	*1	✓		-	-	-	-	-
SW8	DDRBKUP-B	C	OFF	OFF	OFF	OFF	-	-	-	-
SW9	TRST#	S			✓	-	-	-	-	-
SW10	MODESW-A	C	ON	ON	ON	ON	ON	ON	OFF	ON
SW11	MODESW-B	C	OFF	ON	ON	ON*2	ON	ON	ON	ON
SW12	MODESW-C	C	OFF	ON	ON	ON	ON	ON	ON	ON
SW14	SSI78-M/S	S	✓	-		-	-	-	-	-
SW15	USB-SW	S	✓			-	-	-	-	-
SW16	SDHI0/DBG2-A	C	✓	-		-	-	-	-	-
JP2	SDHI0/DBG2-B	C	✓	-		-	-	-	-	-
SW28	VDDQVA_SD0	S	OFF	-	-	-	-	-	-	-
SW17	LVDS	C		✓	-	-	-	-	-	-
SW20	TACTSW0	C	Tactile SW	-	-	-	-	-	-	-
SW21	TACTSW1	C	Tactile SW	-	-	-	-	-	-	-
SW22	TACTSW2	C	Tactile SW	-	-	-	-	-	-	-
SW23	ACCSW	C		-	✓ (OFF)	-	-	-	-	-
SW27	PRESET#	C	Push SW	-	-	-	-	-	-	-
SW29	MIPI-SW	S	ON	ON	-	-	-	-	-	-
SW30	PHYAD	C	OFF	OFF	-	-	-	-	-	-
SW31*3	GPIO/USB	S	ON	ON	OFF	OFF	OFF	OFF	-	-

C: Component side of the board, S: Solder side of the board

*1: From Yocto BSP v2.12.0, it is necessary to enable BKUP_TRG signal for Suspend to RAM, please set SW7 Pin-1.

*2: If debugger is connected, please set SW11-4 pin off.

*3: The SW31 exists in Salvator-XS board only.

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Table 3 setting of Dip switches (R-Car E3 System Evaluation Board Ebisu, and Ebisu-4D)

Switch Number	Switch Name	Pin1	Pin2	Pin3	Pin4	Pin5	Pin6	Pin7	Pin8
SW1	QSPI-A	OFF	OFF	OFF	OFF	OFF	OFF	-	-
SW2	QSPI-B	OFF	OFF	OFF	OFF	OFF	OFF	-	-
SW3	QSPI-C		✓ (ON)	-	-	-	-	-	-
SW31	QSPI-D		✓ (ON)	-	-	-	-	-	-
SW13	QSPI-E	✓	-		-	-	-	-	-
(SW42)	QSPI-F	---	---	-	-	-	-	-	-
SW4	SOFTSW	OFF	OFF	OFF	OFF	-	-	-	-
SW10	MODESW-A	ON	OFF	OFF	ON	ON	ON	OFF	ON
SW11	MODESW-B	OFF	ON	OFF	ON*1	ON	ON	ON	ON
SW12	MODESW-C	ON	ON	ON	ON	ON	-	-	-
SW14	SSI34-M/S	✓	-		-	-	-	-	-
SW15	USB-SW	✓			-	-	-	-	-
SW16	SDHI0/JTAG2-A	✓	-		-	-	-	-	-
JP2	SDHI0/JTAG2-B	✓	-		-	-	-	-	-
SW28	VDDQ_SD0	OFF	-	-	-	-	-	-	-
SW17	LVDS0-DIR		✓	-	-	-	-	-	-
SW48	LVDS1-DIR		✓	-	-	-	-	-	-
SW44	LVDS0-SEL	ON	ON	-	-	-	-	-	-
SW47	LVDS1-SEL	✓ (OFF)		-	-	-	-	-	-
SW45	LVDS-LNK		✓ (ON)	-	-	-	-	-	-
SW50	LVDS-DK			✓	-	-	-	-	-
SW29	MIPI-SW		✓	-	-	-	-	-	-
SW49	PCIe/EXIO_A	✓ (OFF)		-	-	-	-	-	-
SW23	ACCSW		-	✓ (OFF)	-	-	-	-	-
SW36	PRESET#	Push SW	-	-	-	-	-	-	-
SW20	PUSHSW0	Push SW	-	-	-	-	-	-	-
SW21	PUSHSW1	Push SW	-	-	-	-	-	-	-
SW22	PUSHSW2	Push SW	-	-	-	-	-	-	-
JP1	V_TEST	Open	-	-	-	-	-	-	-
JP6	VDDQ25_AVB0	✓	-		-	-	-	-	-
JP7	VDDQ_DDR	✓	-		-	-	-	-	-
(JP8)	PWR-A	-	-	---	-	---	-	-	-
(JP9)	PWR-B	---	-	-	-	-	-	-	-
(JP10)	PWR-C	---	-	-	-	-	-	-	-

*1: If debugger is connected, please set SW11-4 pin off.

3. Building Instructions

You can build BSP by using Yocto Project. Please execute following steps in `${WORK}` directory on Linux Host PC. Filesystem by making following instruction is the one for testing current BSP package in Renesas. Please note that Renesas has not been verified with any other build configuration or modified recipes except “core-image-weston” configuration which is based on upstream Yocto Project deliverables and some additional packages correspond to gstreamer.

Note) Renesas executed following instructions with clean `${WORK}/build` directory. You may use `wipe-sysroot` and/or `bitbake -c cleansstate` to reflect modifications of configuration files for Recipe as in open source Yocto Project’s standards, however Renesas strongly recommends to use recipe with clean `${WORK}/build` directory for each configurations because there are some implicit dependency for header files exist to keep compatibility between application build scheme with/without proprietary software.

Step 1 installation of required commands

Ubuntu is used as Linux Host PC since Yocto Project Quick Start specifies Ubuntu as one of the distribution. In case of that you can install the required commands as follows.

Please refer to <http://www.yoctoproject.org/docs/current/yocto-project-qs/yocto-project-qs.html> for detail.

```
$ sudo apt-get install gawk wget git-core diffstat unzip texinfo gcc-multilib \  
build-essential chrpath socat cpio python3 python3-pip python3-pexpect \  
xz-utils debianutils iputils-ping python3-git python3-jinja2 libegl1-mesa \  
libSDL1.2-dev pylint3 xterm
```

Note) There is a bitbake command in `${WORK}/poky/scripts/`. Command path is available after step 6.

Note) When you use terminal interactions to build such as `menuconfig` under non-X terminal (ssh, etc.), please install “screen” command package to Host PC.

Note) Please set up user name and e-mail in Git. You can set up with ‘`git config --global`’. Please refer to online manual for git command.

Note) In Renesas environment, Ubuntu version is 16.04 LTS and git version is 2.7.4.

Step 2 download of required files

Required files (poky) are downloaded by git clone.

```
$ cd ${WORK}  
$ git clone git://git.yoctoproject.org/poky  
$ git clone git://git.openembedded.org/meta-openembedded  
$ git clone git://github.com/renesas-r-car/meta-renesas.git
```

Step 3 checkout

Please checkout available version of each git clone.

```
$ cd ${WORK}/poky  
$ git checkout -b tmp 5e1f52edb7a9f790fb6cb5d96502f3690267c1b1  
  
$ cd ${WORK}/meta-openembedded  
$ git checkout -b tmp 9e60d30669a2ad0598e9abf0cd15ee06b523986b  
  
$ cd ${WORK}/meta-renesas  
$ git checkout -b tmp f6ccae7cfb669937aac221ff5cb6a13b36eff951
```

Note) tmp is a temporary name of a local branch. We can use checkout command without branch. Please note that HEAD refers directly to commit (detached HEAD).

3.1 In case of BSP + 3D Graphics + Multimedia package

When you use proprietary Multimedia and 3D Graphics software from Renesas, please execute as following steps. Otherwise please skip to section 3.2 or 3.3.

Step 4 copy proprietary software into recipe directory structure

To use licensed 3D graphics software and Multimedia package from Renesas, please copy deliverables of those software into recipe directory structure. Renesas provide shell script to copy those software.

Copy All Proprietary Software Packages to \${PKGS_DIR}:

```
$ mkdir ${PKGS_DIR}
```

```
$ cp <zip of Proprietary Software Package> ${PKGS_DIR}
```

Install them into recipe directory structure by shell script:

```
$ cd ${WORK}/meta-renesas
```

```
$ sh \
```

```
meta-rcar-gen3/docs/sample/copyscript/copy_proprietary_softwares.sh \
```

```
${PKGS_DIR}
```

Note) Subdirectory is not supporting in \${PKGS_DIR}. Please store all packages on the root of \${PKGS_DIR}.

Note) Please use regular alphanumeric file name ([A-Za-z0-9_] e.g.) for \${PKGS_DIR} due to restrictions of current copy script.

Step 5 execute source command

Please execute source command with oe-init-build-env for setting environment.

```
$ cd ${WORK}
```

```
$ source poky/oe-init-build-env
```

Step 6 copy bblayers.conf and local.conf

Please copy configuration files from deliverables.

```
$ cp ${WORK}/meta-renesas/meta-rcar-gen3/docs/sample/conf/<supported  
board name>/poky-gcc/mmp/*.conf ./conf/.
```

Note) <supported board name> is the one of the following: salvator-x, ebisu.

Step 7 enable 3D Graphics and Multimedia package to install GSX modules

To enable 3D Graphics packages which use GSX, please overwrite local.conf as following instructions or modify local.conf as descriptions in \${WORK}/meta-renesas/meta-rcar-gen3/README.proprietary.md.

To install GSX kernel module:**Overwrite local.conf**

```
$ cp conf/local-wayland.conf conf/local.conf (For Wayland)
```

Step 8 enable Multimedia package

Please modify configurations in `${WORK}/build/conf/local.conf` by following instructions.

Note) Please refer to `${WORK}/meta-renesas/meta-rcar-gen3/README.proprietary.md`.

The following standard multimedia packages are enabled

No.	Functions	Explanation
1	MMNGR	Memory manager driver & shared libraries
2	VSPM	VSP driver & FDP driver & shared libraries
3	VSP2	VSP2 driver
4	OMX	OMX common parts

To enable optional multimedia functions, please add `DISTRO_FEATURES_append` to `${WORK}/build/conf/local.conf` as `DISTRO_FEATURES_append = "<function name>"`.

Note) These configurations exist near the end of `local.conf`.

Note) `DISTRO_FEATURES_append` are commented out by the default. To enable functions, please uncomment it.

For example**[Disable]**

```
#DISTRO_FEATURES_append = " h263dec_lib"
```

[Enable (default)]

```
DISTRO_FEATURES_append = " h263dec_lib"
```


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The following list is package name to enable/disable as optional multimedia functions

No.	Function name	Default value	Explanation
1	h264dec_lib	Enable	H264 decoder library RTM0AC0000XV264D30SL41C
2	h264enc_lib	Disable	H264 encoder library RTM0AC0000XV264E30SL41C
3	h265dec_lib	Disable	H265 decoder library RTM0AC0000XV265D30SL41C
4	mpeg2dec_lib	Disable	MPEG2 decoder library RTM0AC0000XVM2VD30SL41C
5	mpeg4dec_lib	Disable	MPEG4 decoder library RTM0AC0000XVM4VD30SL41C
6	vc1dec_lib	Disable	VC-1 decoder library RTM0AC0000XVVC1D30SL41C
7	h263dec_lib	Disable	H263 decoder library RTM0AC0000XV263D30SL41C
8	divxdec_lib	Disable	DivX decoder library RTM0AC0000XVDVXD30SL41C
9	rvdec_lib	Disable	RealVideo decoder library RTM0AC0000XVRLVD30SL41C
10	aacldcdec_lib	Enable	AAC-LC decoder library RTM0AC0000XAAACD30SL41C
11	aacldcdec_mdw	Enable	AAC-LC 2ch decoder middleware library RTM0AC0000ADAACMZ1SL41C
12	aacpv2dec_lib	Disable	aacPlus V2 Decoder Library RTM0AC0000XAAAPD30SL41C
13	aacpv2dec_mdw	Disable	aacPlus V2 Decoder Middleware Library RTM0AC0000ADAAPMZ1SL41C
14	mp3dec_lib	Disable	MP3 decoder library RTM0AC0000XAMP3D30SL41C
15	mp3dec_mdw	Disable	MP3 decoder middleware library RTM0AC0000ADMP3MZ1SL41C
16	wmadec_lib	Disable	WMA decoder library RTM0AC0000XAWMAD30SL41C
17	wmadec_mdw	Disable	WMA decoder middleware library RTM0AC0000ADWMAMZ1SL41C
18	aaclcenc_lib	Disable	AAC-LC encoder library RTM0AC0000XAAACE30SL41C
19	aaclcenc_mdw	Disable	AAC-LC encoder middleware library RTM0AC0000AEAACMZ1SL41C
20	flacdec_lib	Disable	FLAC decoder library RTM0AC0000XAFLAD30SL41C
21	alacdec_lib	Disable	ALAC decoder library RTM0AC0000XAALAD30SL41C
22	dddec_lib	Disable	Dolby(R) Digital decoder library RTM0AC0000XADD5D30SL41C

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No.	Function name	Default value	Explanation
23	dddec_mdw	Disable	Dolby(R) Digital decoder middleware library RTM0AC0000ADDD5MZ1SL41C
24	vp8dec_lib	Disable	Media Component VP8 Decoder Library for Linux RTM0AC0000XVVP8D30SL41C
25	vp8enc_lib	Disable	Media Component VP8 Encoder Library for Linux RTM0AC0000XVVP8E30SL41C
26	vp9dec_lib	Disable	Media Component VP9 Decoder Library for Linux RTM0AC0000XVVP9D30SL41C
27	cmsbcm	Disable	Basic Color Management Middleware for Linux RTM0AC0000JRCMBCV0SL41C
28	cmsbhc	Disable	CMM3 Backlight Control Middleware for Linux RTM0AC0000JRCMBLC0SL41C
29	cmsdgc	Disable	VSP2 Dynamic Gamma Correction Middleware for Linux RTM0AC0000JRCMDGV0SL41C
30	adsp	Disable	ADSP Interface for Linux RCG3AHIFL4101ZDP
31	avb	Disable	Ether-AVB

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The following list is dependent package name

No.	Function name	Type Name	Dependent Packages
1	h264dec_lib	RTM0AC0000XV264D30SL41C	RTM0AC0000XVCMND30SL41C RTM0AC0000XCMCTL30SL41C RCG3VUDRL4101ZDO
2	h264enc_lib	RTM0AC0000XV264E30SL41C	RTM0AC0000XVCMNE30SL41C RTM0AC0000XCMCTL30SL41C RCG3VUDRL4101ZDO
3	h265dec_lib	RTM0AC0000XV265D30SL41C	RTM0AC0000XVCMND30SL41C RTM0AC0000XCMCTL30SL41C RCG3VUDRL4101ZDO
4	mpeg2dec_lib	RTM0AC0000XVM2VD30SL41C	RTM0AC0000XVCMND30SL41C RTM0AC0000XCMCTL30SL41C RCG3VUDRL4101ZDO
5	mpeg4dec_lib	RTM0AC0000XVM4VD30SL41C	RTM0AC0000XVCMND30SL41C RTM0AC0000XCMCTL30SL41C RCG3VUDRL4101ZDO
6	vc1dec_lib	RTM0AC0000XVVC1D30SL41C	RTM0AC0000XVCMND30SL41C RTM0AC0000XCMCTL30SL41C RCG3VUDRL4101ZDO
7	h263dec_lib	RTM0AC0000XV263D30SL41C	RTM0AC0000XVCMND30SL41C RTM0AC0000XCMCTL30SL41C RCG3VUDRL4101ZDO
8	divxdec_lib	RTM0AC0000XVDVXD30SL41C	RTM0AC0000XVCMND30SL41C RTM0AC0000XCMCTL30SL41C RCG3VUDRL4101ZDO
9	rvdec_lib	RTM0AC0000XVRLVD30SL41C	RTM0AC0000XVCMND30SL41C RTM0AC0000XCMCTL30SL41C RCG3VUDRL4101ZDO
10	aacldec_lib	RTM0AC0000XAAACD30SL41C	RTM0AC0000XCMCTL30SL41C RTM0AC0000XACMND30SL41C RTM0AC0000ADAACMZ1SL41C
11	aacldec_mdw	RTM0AC0000ADAACMZ1SL41C	-
12	aacpv2dec_lib	RTM0AC0000XAAAPD30SL41C	RTM0AC0000XCMCTL30SL41C RTM0AC0000XACMND30SL41C RTM0AC0000ADAAPMZ1SL41C
13	aacpv2dec_mdw	RTM0AC0000ADAAPMZ1SL41C	-
14	mp3dec_lib	RTM0AC0000XAMP3D30SL41C	RTM0AC0000XCMCTL30SL41C RTM0AC0000XACMND30SL41C RTM0AC0000ADMP3MZ1SL41C
15	mp3dec_mdw	RTM0AC0000ADMP3MZ1SL41C	-
16	wmadec_lib	RTM0AC0000XAWMAD30SL41C	RTM0AC0000XCMCTL30SL41C RTM0AC0000XACMND30SL41C RTM0AC0000ADWMAMZ1SL41C
17	wmadec_mdw	RTM0AC0000ADWMAMZ1SL41C	-
18	aaclcenc_lib	RTM0AC0000XAAACE30SL41C	RTM0AC0000XCMCTL30SL41C RTM0AC0000XACMND30SL41C RTM0AC0000AEAACMZ1SL41C

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No.	Function name	Type Name	Dependent Packages
19	aacdec_mdw	RTM0AC0000AEAACMZ1SL41C	-
20	flacdec_lib	RTM0AC0000XAFLAD30SL41C	RTM0AC0000XCMCTL30SL41C RTM0AC0000XACMND30SL41C RCG3AFLDL4101ZDO
21	alacdec_lib	RTM0AC0000XAALAD30SL41C	RTM0AC0000XCMCTL30SL41C RTM0AC0000XACMND30SL41C RCG3AFLDL4101ZDO
22	dddec_lib	RTM0AC0000XADD5D30SL41C	RTM0AC0000XCMCTL30SL41C RTM0AC0000XACMND30SL41C RTM0AC0000ADDD5MZ1SL41C
23	dddec_mdw	RTM0AC0000ADDD5MZ1SL41C	-
24	cmsbcm	RTM0AC0000JRCMBCV0SL41C	-
25	cmsblc	RTM0AC0000JRCMBLC0SL41C	-
26	cmsdgc	RTM0AC0000JRCMDGV0SL41C	-
27	adsp	RCG3AHIFL4101ZDP	RCG3AHPDL4101ZDO RCG3AHFWN0201ZDP
28	avb	-	-

Step 9 select SoC

In case of Salvator X/XS board, please set SOC_FAMILY in \${WORK}/build/conf/local.conf as SOC_FAMILY = “<soc type name>”.

```
[H3]
SOC_FAMILY = "r8a7795"
[M3]
SOC_FAMILY = "r8a7796"
[M3N]
SOC_FAMILY = "r8a77965"
```

In case of Ebisu board, there is no need to set SOC_FAMILY in \${WORK}/build/conf/local.conf because it was already added in machine config: ebisu.conf.

Step 10 building with bitbake

Please build as follows. The file system (core-image-weston-<supported board name>.tar.bz2) is created in \${WORK}/build/tmp/deploy/images/<supported board name>/ directory.

Note) <supported board name> is the one of the following: salvator-x, ebisu.

Note) Build by bitbake might need several hours under the influence of Linux Host PC performance and network environment.

Note) The bitbake downloads some package while building. Then the bitbake might stop for network timeout or link error. In this case, please get applicable package in \${WORK}/build/downloads directory whenever build stops by wget command, or please review timeout definitions of package download (wget, etc.) described in \${WORK}/poky/meta/conf/bitbake.conf.

```
$ cd ${WORK}/build
$ bitbake core-image-weston (for Wayland)
```

3.2 In case of BSP + 3D Graphics (without Multimedia package)

When you use licensed 3D Graphics software but will not use proprietary Multimedia software from Renesas, please execute as following steps. Otherwise please skip to section 3.3.

Step 4 copy proprietary software into recipe directory structure

To use licensed 3D graphics software and Multimedia package from Renesas, please copy deliverables of those software into recipe directory structure. Renesas provide shell script to copy those software.

Copy All Proprietary Software Packages to \${PKGS_DIR}:

```
$ mkdir ${PKGS_DIR}
```

```
$ cp <zip of Proprietary Software Package> ${PKGS_DIR}
```

Install them into recipe directory structure by shell script:

```
$ cd ${WORK}/meta-renesas
```

```
$ sh \
```

```
meta-rcar-gen3/docs/sample/copyscript/copy_proprietary_softwares.sh \  
${PKGS_DIR}
```

Note) Subdirectory is not supporting in \${PKGS_DIR}. Please store all packages on the root of \${PKGS_DIR}.

Note) Please use regular alphanumeric file name ([A-Za-z0-9_] e.g.) for \${PKGS_DIR} due to restrictions of current copy script.

Step 5 execute source command

Please execute source command with oe-init-build-env for setting environment.

```
$ cd ${WORK}
```

```
$ source poky/oe-init-build-env
```

Step 6 copy bblayers.conf and local.conf

Please copy configuration files from deliverables.

```
$ cp ${WORK}/meta-renesas/meta-rcar-gen3/docs/sample/conf/<supported  
board name>/poky-gcc/gfx-only/*.conf ./conf/.
```

Note) <supported board name> is the one of the following: salvator-x, ebisu.

Step 7 enable 3D Graphics package to install GSX modules

To enable 3D Graphics packages which use GSX, please overwrite local.conf as following instructions or modify local.conf as descriptions in \${WORK}/meta-renesas/meta-rcar-gen3/README.proprietary.md.

To install GSX kernel module:**Overwrite local.conf**

```
$ cp conf/local-wayland.conf conf/local.conf (For Wayland)
```

Step 8 select SoC

In case of Salvator-X/XS board, please set SOC_FAMILY in \${WORK}/build/conf/local.conf as SOC_FAMILY = "<soc type name>".

```
[H3]
SOC_FAMILY = "r8a7795"
[M3]
SOC_FAMILY = "r8a7796"
[M3N]
SOC_FAMILY = "r8a77965"
```

In case of Ebisu board, there is no need to set SOC_FAMILY in \${WORK}/build/conf/local.conf because it was already added in machine config: ebisu.conf.

Step 9 building with bitbake

Please build as follows. The file system (core-image-weston-<supported board name>.tar.bz2) is created in \${WORK}/build/tmp/deploy/images/<supported board name>/ directory.

Note) <supported board name> is the one of the following: salvator-x, ebisu.

Note) Build by bitbake might need several hours under the influence of Linux Host PC performance and network environment.

Note) The bitbake downloads some package while building. Then the bitbake might stop for network timeout or link error. In this case, please get applicable package in \${WORK}/build/downloads directory whenever build stops by wget command, or please review timeout definitions of package download (wget, etc.) described in \${WORK}/poky/meta/conf/bitbake.conf.

```
$ cd ${WORK}/build
$ bitbake core-image-weston (for Wayland)
```

3.3 In case of BSP Only

When you will not use neither proprietary Multimedia software nor licensed 3D Graphics software from Renesas, please execute as following steps.

Step 4 execute source command

Please execute source command with oe-init-build-env for setting environment.

```
$ cd ${WORK}  
$ source poky/oe-init-build-env
```

Step 5 copy bblayers.conf and local.conf

Please copy configuration files from deliverables.

```
$ cp ${WORK}/meta-renesas/meta-rcar-gen3/docs/sample/conf/<supported  
board name>/poky-gcc/bsp/*.conf ./conf/.
```

Note) <supported board name> is the one of the following: salvator-x, ebisu.

Note) core-image-weston is not supported even though local-wayland.conf is provided.

Step 6 select SoC

In case of Salvator-X/XS board, please set SOC_FAMILY in \${WORK}/build/conf/local.conf as SOC_FAMILY = "<soc type name>".

```
[H3]  
SOC_FAMILY = "r8a7795"  
[M3]  
SOC_FAMILY = "r8a7796"  
[M3N]  
SOC_FAMILY = "r8a77965"
```

In case of Ebisu board, there is no need to set SOC_FAMILY in \${WORK}/build/conf/local.conf because it was already added in machine config: ebisu.conf.

Step 7 building with bitbake

Please build as follows. The file system (core-image-minimal-<supported board name>.tar.bz2) is created in \${WORK}/build/tmp/deploy/images/<supported board name>/ directory.

Note) <supported board name> is the one of the following: salvator-x, ebisu.

Note) Build by bitbake might need several hours under the influence of Linux Host PC performance and network environment.

Note) The bitbake downloads some package while building. Then the bitbake might stop for network timeout or link error. In this case, please get applicable package in \${WORK}/build/downloads directory whenever build stops by wget command, or please review timeout definitions of package download (wget, etc.) described in \${WORK}/poky/meta/conf/bitbake.conf.

```
$ cd ${WORK}/build  
$ bitbake core-image-minimal
```

4. Writing of IPL/Secure

4.1 Writing data

Filename	Program Top Address	Flash Save Address	Description
bootparam_sa0*	0xE6320000	0x000000	Loader(Boot parameter)
bl2-*	0xE6304000	0x040000	Loader
cert_header_sa6*	0xE6320000	0x180000	Loader(Certification)
bl31-*	0x44000000	0x1C0000	ARM Trusted Firmware
tee-*	0x44100000	0x200000	OP-Tee
u-boot-elf-*	0x50000000	0x640000	U-Boot

Note) U-Boot/IPL for Salvator-XS, Salvator-X, Ebisu and Ebisu-4D are as follows:

Board	SoC	DDR	U-Boot/IPL
Salvator-XS	H3	8GB (2GB x 4ch)	bl2-salvator-x-4x2g.srec bl31-salvator-x-4x2g.srec bootparam_sa0-4x2g.srec cert_header_sa6-4x2g.srec tee-salvator-x.srec u-boot-elf-salvator-xs-4x2g.srec
		4GB (1GB x 4ch)	bl2-salvator-x.srec bl31-salvator-x.srec bootparam_sa0.srec cert_header_sa6.srec tee-salvator-x.srec u-boot-elf-salvator-xs.srec
	M3	4GB	bl2-salvator-x.srec bl31-salvator-x.srec bootparam_sa0.srec cert_header_sa6.srec tee-salvator-x.srec u-boot-elf-salvator-xs.srec
		8GB (4GB x 2ch)	bl2-salvator-x.srec bl31-salvator-x.srec bootparam_sa0.srec cert_header_sa6.srec tee-salvator-x.srec u-boot-elf-salvator-xs-2x4g.srec
	M3N	2GB	bl2-salvator-x.srec bl31-salvator-x.srec bootparam_sa0.srec cert_header_sa6.srec tee-salvator-x.srec u-boot-elf-salvator-xs.srec
Salvator-X	H3	4GB (1GB x 4ch)	bl2-salvator-x.srec bl31-salvator-x.srec bootparam_sa0.srec cert_header_sa6.srec tee-salvator-x.srec u-boot-elf-salvator-x.srec
	M3	4GB	bl2-salvator-x.srec bl31-salvator-x.srec bootparam_sa0.srec cert_header_sa6.srec tee-salvator-x.srec u-boot-elf-salvator-x.srec
	M3N	2GB	bl2-salvator-x.srec bl31-salvator-x.srec bootparam_sa0.srec cert_header_sa6.srec tee-salvator-x.srec u-boot-elf-salvator-x.srec

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Ebisu	E3	1GB	bl2-ebisu.srec bl31-ebisu.srec bootparam_sa0.srec cert_header_sa6.srec tee-ebisu.srec u-boot-elf-ebisu.srec
Ebisu-4D	E3	2GB	bl2-ebisu-4d.srec bl31-ebisu-4d.srec bootparam_sa0-4d.srec cert_header_sa6-4d.srec tee-ebisu.srec u-boot-elf-ebisu-4d.srec

Note) Please refer to Chapter 5 for U-Boot.

4.2 Dip-Switch

a) QSPI Mode

Switch Number	Switch Name	Pin1	Pin2	Pin3	Pin4	Pin5	Pin6	Pin7	Pin8
SW1	QSPI-A	ON	ON	ON	ON	ON	ON	-	-
SW2	QSPI-B	ON	ON	ON	ON	ON	ON	-	-
SW3	QSPI-C	set(OFF)		-	-	-	-	-	-
SW10	MODESW-A	Refer to 2.2				ON	OFF	ON	ON
SW31*1	QSPI-D	OFF	-	-	-	-	-	-	-

*1: Only E3 System Evaluation Board needs to set SW31.

b) Hyper Flash Mode

Switch Number	Switch Name	Pin1	Pin2	Pin3	Pin4	Pin5	Pin6	Pin7	Pin8
SW1	QSPI-A	OFF	OFF	OFF	OFF	OFF	OFF	-	-
SW2	QSPI-B	OFF	OFF	OFF	OFF	OFF	OFF	-	-
SW3	QSPI-C		Set(ON)	-	-	-	-	-	-
SW10	MODESW-A	Refer to 2.2							
SW31*1	QSPI-D	ON	-	-	-	-	-	-	-

*1: Only E3 System Evaluation Board needs to set SW31.

4.3 How to write

Please connect R-Car H3/M3/E3 System Evaluation Board, Windows Host PC with terminal software for console and Linux Host PC.

In case of R-Car H3/M3/M3N/E3, Ethernet connector is CN22, serial connector is CN25.

Step 1 connect cable

Connect USB Host connector of Windows Host PC that is virtual COM port to CN25 of R-Car H3/M3/E3 System Evaluation Board with USB cable for displaying console.

Step 2 setting the terminal software

Activate the Terminal Software on Windows Host PC. Configure the Terminal Software on Windows Host PC as followings. Please refer to Table 1 about the VCP driver for making a USB host connector into a virtual COM port.

[setting value] baud rate 115200, 8bit data, parity none, stop 1 bit, flow control none.

Step 3 write data file to Hyper Flash

A file is written in Hyper Flash in the following procedures.

- Set dip switch “QSPI Mode”.
- Reset board then start mini monitor.
- Set dip switch (Select Hyper Flash)
SW1: ALL OFF
SW2: ALL OFF
SW3: ON
SW31: ON (R-Car M3 Kriek and R-Car E3)
Note) SW10 does not need to change.
- Execute xls2 command (load program to flash).

R-Car Gen3 Sample Loader V3.03 2017.08.25**For Salvator , Kriek , and StarterKit.****Board Judge : Used Board-ID****DDR_Init : boardcnf[7] Salvator / Starter Kit (H3SIP_VER2.0)****INITIAL SETTING : Salvator-XS / R-Car H3 ES3.0****CPU : AArch64 CA57****DRAM : LPDDR4 DDR3200****DEVICE : QSPI Flash(S25FS128) at 40MHz DMA****BOOT : Normal Boot****BACKUP : DDR Cold Boot****jump to 0xE6330000****R-Car Gen3 MiniMonitor V3.03 2017.08.25****Work Memory : SystemRAM****Board Name : Salvator-XS****Product Code : R-Car H3 ES3.0****>xls2****===== Qspi/HyperFlash writing of Gen3 Board Command =====****Load Program to Spiflash****Writes to any of SPI address.****Please select,FlashMemory.****1 : QspiFlash (U5 : S25FS128S)****2 : QspiFlash Board (CN3: S25FL512S)****3 : HyperFlash (SiP internal)****Select (1-3)>**

- Select HyperFlash. Input “3”.
- After "SW1 SW2 All OFF! Setting OK? (Push Y key)" is displayed, input "y".
- After "SW3 ON! Setting OK? (Push Y key)" is displayed, input "y".
- After "SW31 ON! Setting OK? (Push Y key)" is displayed, input "y". (R-Car E3 only)
- After "SW31 ON! Setting OK? (Push Y key) [In the case of Kriek Board]" is displayed, input "y". (R-Car M3 Kriek only)
- After "Please Input Program Top Address" is displayed, input Program Top Address in 4.1 and "Enter".
- After "Please Input Qspi/HyperFlash Save Address" is displayed, input Flash Save Address in 4.1 and "Enter".
- After "Please send ! ('.' & CR stop load)" is displayed, In case of Tera Term, transmit srec file in 4.1 by "File -> Send file...".
- If there are some data in writing area, "SPI Data Clear(H'FF) Check :H'00000000-0003FFFF Clear OK?(y/n)" is displayed. Then input "y".
- After "SAVE SPI-FLASH complete!" is displayed, the prompt returns. It means finish.
- Please repeat the xls2 command, if other files are written.
- Power OFF.
- Set dip switch to “Hyper Flash Mode”.

Note) SW1, SW2, and SW3 are already Hyper Flash mode. Please set SW10.

4.4 IPL/Secure write

Please write the file described in Chapter 4.1 to Hyper Flash.

The data file is stored in the `${WORK}/build/tmp/deploy/images/<board_name>` directory.

5. Confirm starting of U-Boot and Linux

Please connect R-Car H3/M3/E3 System Evaluation Board, Windows Host PC with terminal software for console and Linux Host PC with TFTP and NFS server as Figure 1. Then please confirm normal starting of U-Boot and Linux with following step. Please refer to 2.2 for dip switch setting.

In case of R-Car H3/M3/M3N/E3, Ethernet connector is CN22, serial connector is CN25, D-Sub connector is CN15.

Step 1 setting Linux Host PC

Please install TFTP server and NFS server in Linux Host PC with apt-get command and so on. Please set /etc/xinetd.d/tftp of TFTP server and /etc/exports of NFS server according to your environment.

Step 2 connect cable

Connect USB Host connector of Windows Host PC that is virtual COM port to CN25 of R-Car H3/M3/E3 System Evaluation Board with USB cable for displaying console.

Step 3 setting the terminal software

Activate the Terminal Software on Windows Host PC. Configure the Terminal Software on Windows Host PC as followings. Please refer to Table 1 about the VCP driver for making a USB host connector into a virtual COM port.

[setting value] baud rate 115200, 8bit data, parity none, stop 1 bit, flow control none.

Step 4 write U-Boot to Hyper Flash

Filename	Program Top Address	Flash Save Address	Description
u-boot-elf-*	0x50000000	0x640000	U-Boot

Note) *: salvator-xs-4x2g.srec, salvator-xs-2x4g.srec, salvator-xs.srec, salvator-x.srec, ebisu.srec, and ebisu-4d.srec.

The data file is stored in the \${WORK}/build/tmp/deploy/images/<board_name> directory.
Refer to Chapter 4.3 Step3 for writing procedure.

Step 5 set U-Boot environment variables

Please refer to 2.2 for dip switch setting.

Please start U-Boot by board reset. Please set and save environment variable as follows.

```
=> setenv ethaddr xx:xx:xx:xx:xx:xx
=> setenv ipaddr 192.168.0.20
=> setenv serverip 192.168.0.1
=> setenv bootcmd 'tftp 0x48080000 Image;tftp 0x48000000
<Device_Tree>;booti 0x48080000 - 0x48000000'
```

Note) For R-Car H3 (SOC_FAMILY r8a7795), the <Device_Tree> are as follow:

- **r8a7795-salvator-x.dtb**: for R-Car H3 Ver.2.0 on Salvator-X board.
- **r8a7795-salvator-xs.dtb**: for R-Car H3 Ver.2.0/3.0 4GB on Salvator-XS board (CH4 CH0:1GB CH1:1GB CH2:1GB CH3:1GB).
- **r8a7795-salvator-xs-4x2g.dtb**: for R-Car H3 Ver.3.0 8GB on Salvator-XS board (CH4 CH0:2GB CH1:2GB CH2:2GB CH3:2GB).
- RCar H3 Ver.3.0 supports Salvator-XS board only.

For R-Car M3 (SOC_FAMILY r8a7796), the <Device_Tree> are as follow:

- **r8a7796-salvator-x.dtb**: for R-Car M3 Ver.1.x on Salvator-X board.
- **r8a7796-salvator-xs.dtb**: for R-Car M3 Ver.1.x on Salvator-XS board.
- **r8a7796-salvator-xs-2x4g.dtb**: for R-Car M3 Ver.3.0 on Salvator-XS board.

For R-Car M3N (SOC_FAMILY r8a77965), the <Device_Tree> are as follow:

- **r8a77965-salvator-x.dtb**: for R-Car M3N Ver.1.1 on Salvator-X board.
- **r8a77965-salvator-xs.dtb**: for R-Car M3N Ver.1.1 on Salvator-XS board.

For R-Car E3 (SOC_FAMILY r8a77990), the <Device_Tree> are as follow:

- **r8a77990-es10-ebisu.dtb**: for R-Car E3 Ver.1.0 on Ebisu board.
- **r8a77990-es10-ebisu-4d.dtb**: for R-Car E3 Ver.1.0 on Ebisu-4D board.
- **r8a77990-ebisu.dtb**: for R-Car E3 Ver.1.1 on Ebisu board.
- **r8a77990-ebisu-4d.dtb**: for R-Car E3 Ver.1.1 on Ebisu-4D board.

Step 6 change the bootargs by U-Boot

To change bootargs which passed to the kernel in boot sequence, please modify it by “setenv bootargs” command of U-Boot.

```
=> setenv bootargs 'rw root=/dev/nfs nfsroot=192.168.0.1:/export/rfs  
ip=192.168.0.20'
```

Note) When you disable big.LITTLE architecture in R-Car H3/M3, please add "maxcpus" in bootargs as follow:

- R-Car H3 : "maxcpus=4"
- R-Car M3 : "maxcpus=2"

It means that Cortex-A53 does not boot in R-Car H3/M3. For additional information, please refer to User's manual of Kernel.

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Step 7 save environment variables

```
=> saveenv
```

Step 8 set file system

Please extract file system (core-image-weston-<supported board name>.tar.bz2). Please export /export directory of NFS server.

```
$ mkdir /export/rfs  
$ cd /export/rfs  
$ sudo tar xvf core-image-weston(minimal)-<supported board name>.tar.bz2
```

Note) <supported board name> is the following: salvator-x, ebisu.

Step 9 start Linux

After board reset, U-Boot is started. After countdown, Linux boot messages are displayed. Please confirm login prompt after Linux boot messages.

Note) When MAC Address is rewritten, it is necessary to reset.

Note) In core-image-weston, please connect input device (keyboard, mouse) to USB port (salvator-x: CN10, ebisu: CN9). In R-Car M3/M3N, only CN10 of USB2_1 port can be used.

6. Exporting Toolchains

Please refer Documents from Yocto Project to export Toolchains such as

<https://www.yoctoproject.org/docs/3.0.2/sdk-manual/sdk-manual.html>.

And please use build target of bitbake as “core-image-weston-sdk -c populate_sdk” to generate package.

Note) When you use “ld” directly but not via gcc (in case of building Kernel, Driver or U-Boot), please disable LDFLAGS with ‘unset LDFLAGS’. Furthermore, in kernel build, ‘make menuconfig’ occurs error by ncurses. In this case, please set PKG_CONFIG_PATH and disable PKG_CONFIG_SYSROOT_DIR.

```
$ export PKG_CONFIG_PATH=$OECORE_NATIVE_SYSROOT/usr/lib/pkgconfig
$ unset PKG_CONFIG_SYSROOT_DIR
```

Note) Please do not use same shell environment to other compilation/debugging purpose (also make menuconfig of linux kernel, e.g.) but cross compilation for R-Car H3/M3/M3N/E3 which shell environment with “source” command to setup environment variables for the SDK. Because some environment variables for cross compilation interferes execution of other tools on the same shell environment.

Example of instruction:

In following examples, it’s assumed that it’s already extracted and prepared recipe environment such as in the instructions of Section 3 (must done just before execution of bitbake, at least). You may reuse \${WORK}/build while you reuse same configuration after executing bitbake as in Section 3 for this purpose.

Step 1 configure architectures of Host PC which are installed this toolchain

Please modify SDKMACHINE description on \${WORK}/build/conf/local.conf.

On \${WORK}/build/conf/local.conf

```
# This variable specified the architecture to build SDK/ADT items for and means
# you can build the SDK packages for architectures other than the machine you are
# running the build on (i.e. building i686 packages on an x86_64 host.
# Supported values are i686 and x86_64
#SDKMACHINE ?= "i686"
SDKMACHINE ?= "x86_64"
```

Note) 32bit Ubuntu 14.04 is not supported.

Step 2 building toolchain package with bitbake

```
$ cd ${WORK}/build
$ bitbake core-image-weston-sdk -c populate_sdk
$ cp tmp/deploy/sdk/poky-glibc-x86_64-core-image-weston-sdk-aarch64-
salvator-x-toolchain-3.0.2.sh (shared dir. where able to access from each
Host PCs)
```

Note) Please perform “bitbake core-image-minimal -c populate_sdk” in BSP Only.

Step 3 Install toolchain on each Host PCs

```
$ sudo (shared dir. where able to access from each Host PCs)/ poky-glibc-
x86_64-core-image-weston-sdk-aarch64-salvator-x-toolchain-3.0.2.sh
```

```
[sudo] password for (INSTALL person): (password of your account)
Enter target directory for SDK (default: /opt/poky/3.0.2): (just a return)
Extracting SDK...done
Setting it up...done
SDK has been successfully set up and is ready to be used.
```

Step 4 setup environment variables for each compilation on each Host PCs

Please setup environment variables as follows or integrate set-up sequence into your build script or Makefile.

```
$ cd (Your working directory)
$ source /opt/poky/3.0.2/environment-setup-aarch64-poky-linux
$ export LDFLAGS=""
$ ${CC} (Your source code).c .....
```

7. Memory map

Following Figure 2 to Figure 16 show memory map of this R-Car H3/M3/M3N/E3 Linux BSP package.

Note)

- The volume of SDRAM is total 8GB (R-Car H3 Ver.3.0 8GB, R-Car M3 Ver.3.0), 4GB (R-Car H3 Ver.3.0 4GB/Ver.2.0, M3 Ver.1.x), 2GB (R-Car M3N/R-Car E3 System Evaluation Board Ebisu-4D), 1GB (R-Car E3 System Evaluation Board Ebisu).
- 2GB from 0x00_4000_0000 to 0x00_BFFF_FFFF is a shadow area from 0x04_0000_0000 to 0x04_7FFF_FFFF.
- The following regions are used as a secure region. It doesn't allow U-Boot and kernel to access those regions.
 - 63MB from 0x00_43F0_0000 to 0x00_47DF_FFFF in SDRAM
 - 16KB from 0x00_E630_0000 to 0x00_E630_3FFF in System RAM
- **In case the configuration of BSP + 3D Graphics + Multimedia package, it doesn't allow to store any data in "CMA for Lossy comp" (default: 0x00_5400_0000 - 0x00_56FF_FFFF) region which is for media playback before kernel boots up. Any data stored in this region are read through the decompression module in AXI-Bus, so a normal data (not a decoded frame) will be corrupted.**

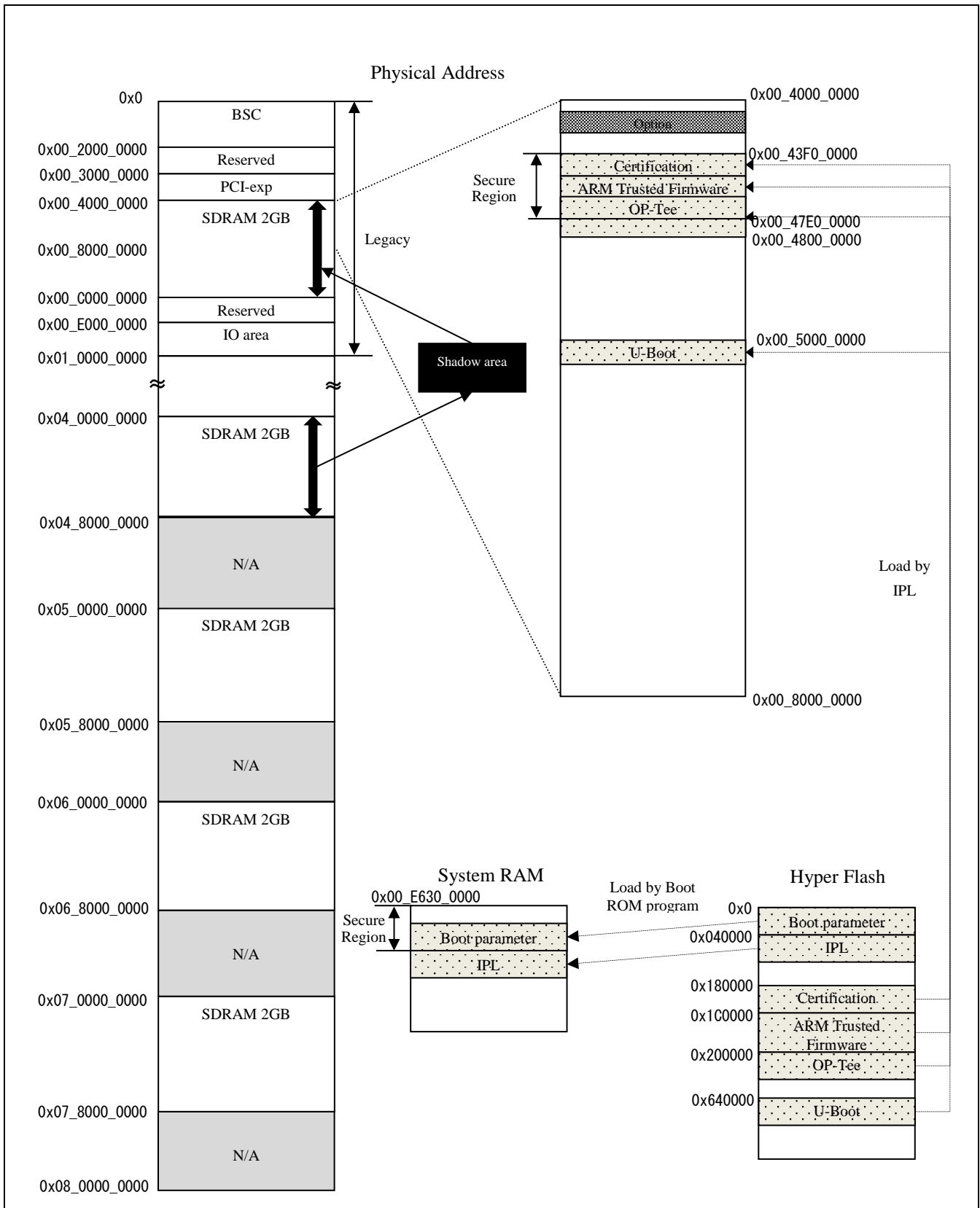


Figure 2. H3 Ver.3.0 8GB memory map (Boot)

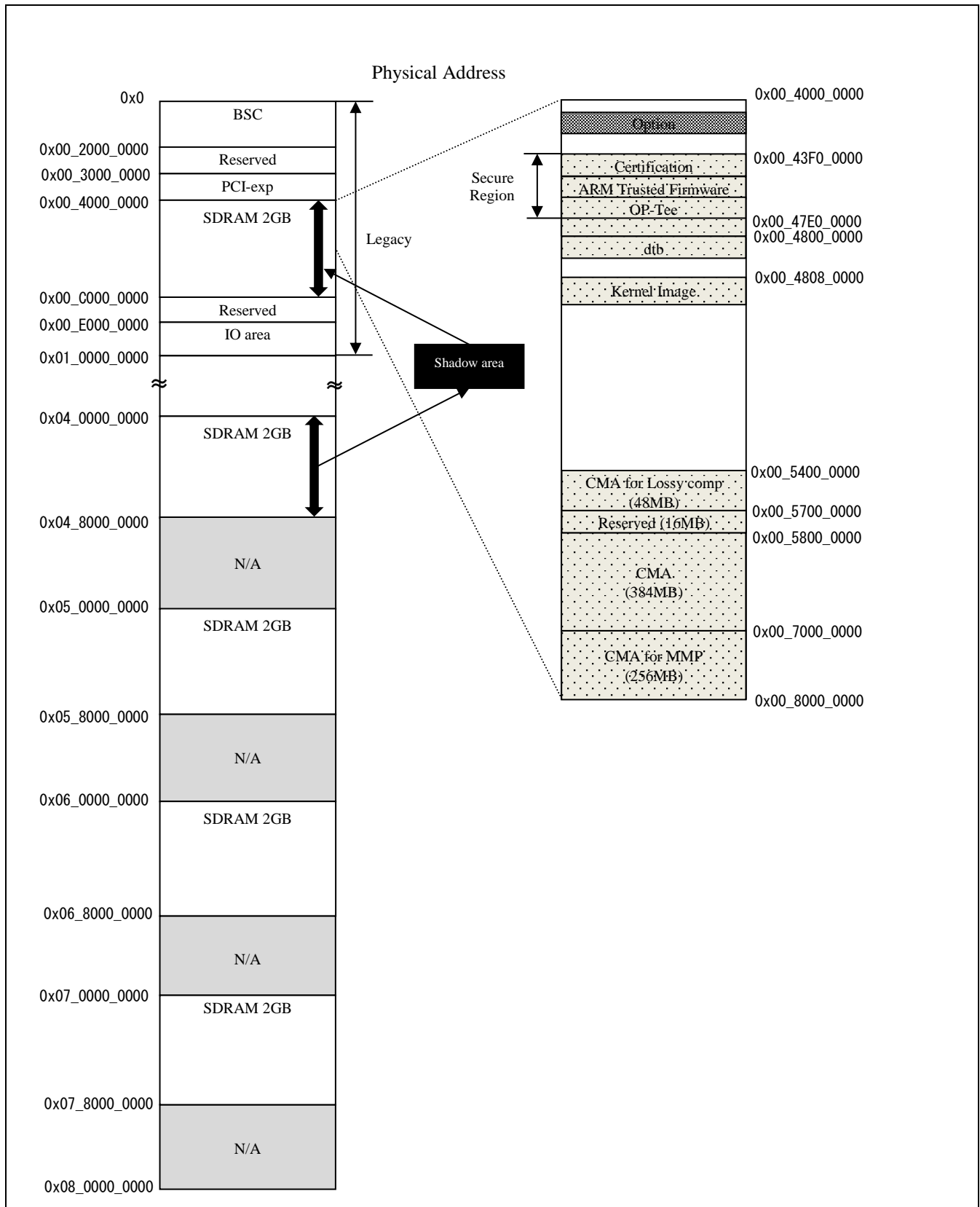


Figure 3. H3 Ver.3.0 8GB memory map (Linux)

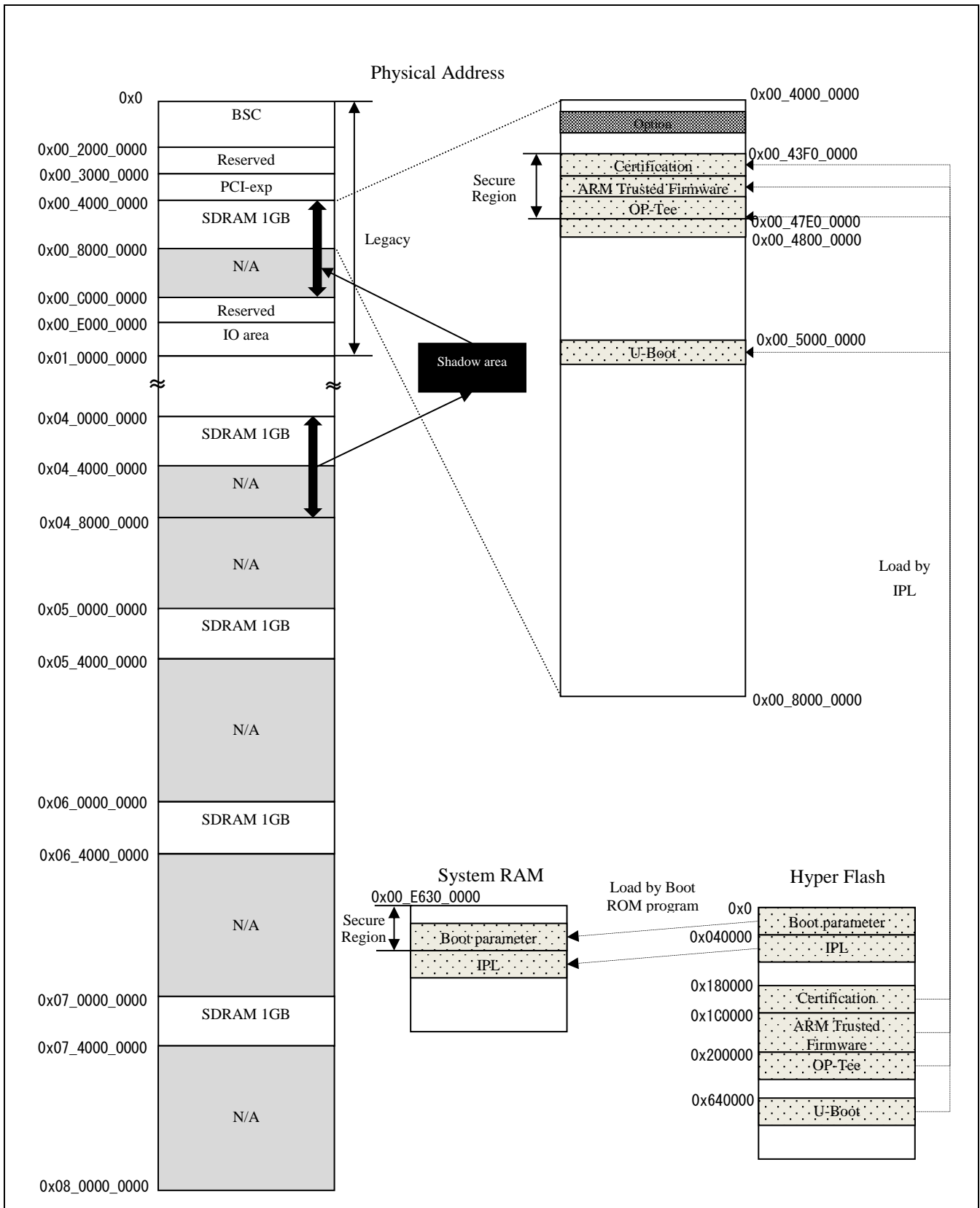


Figure 4. H3 Ver.2.0/Ver.3.0 4GB memory map (Boot)

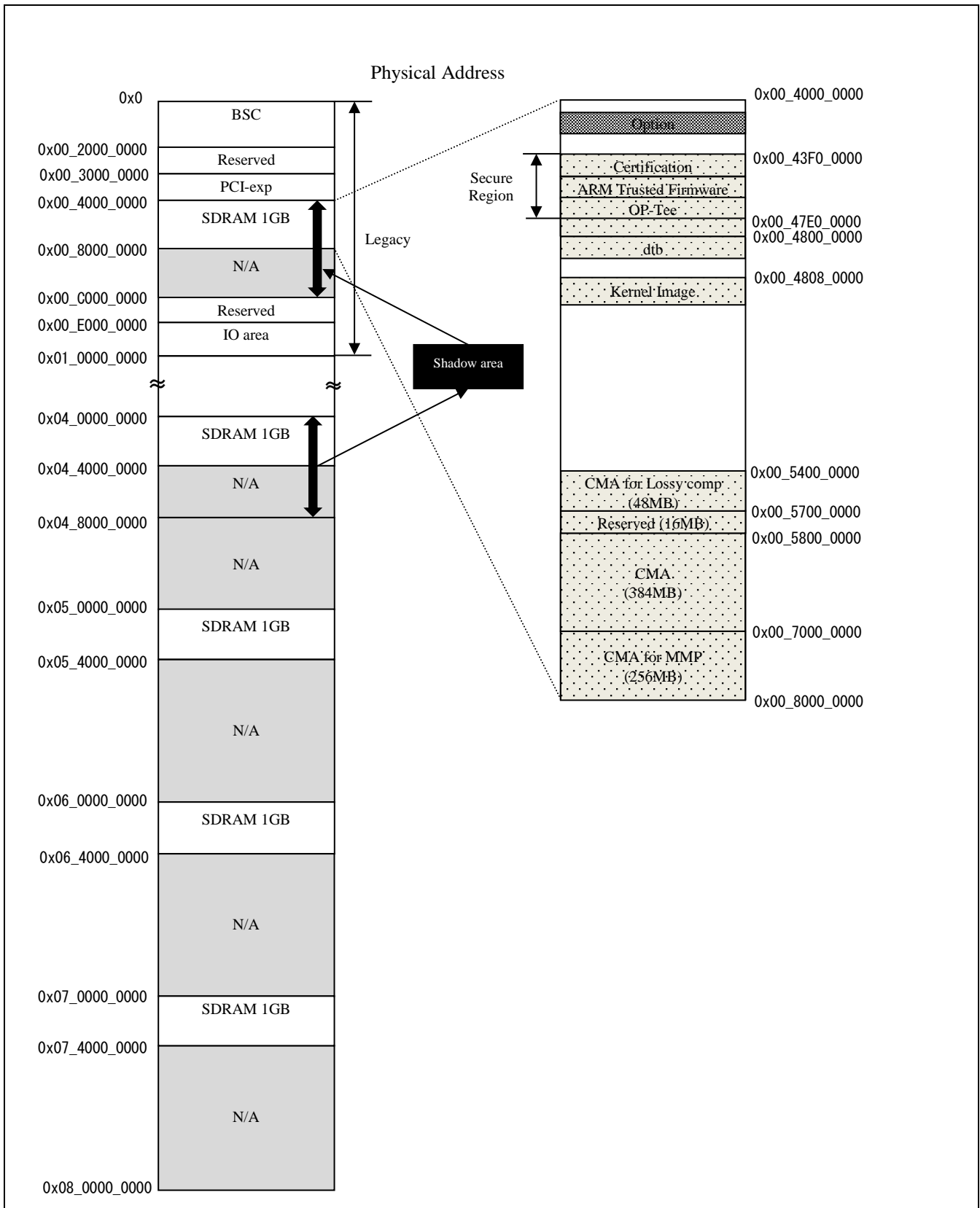


Figure 5. H3 Ver.2.0/Ver.3.0 4GB memory map (Linux)

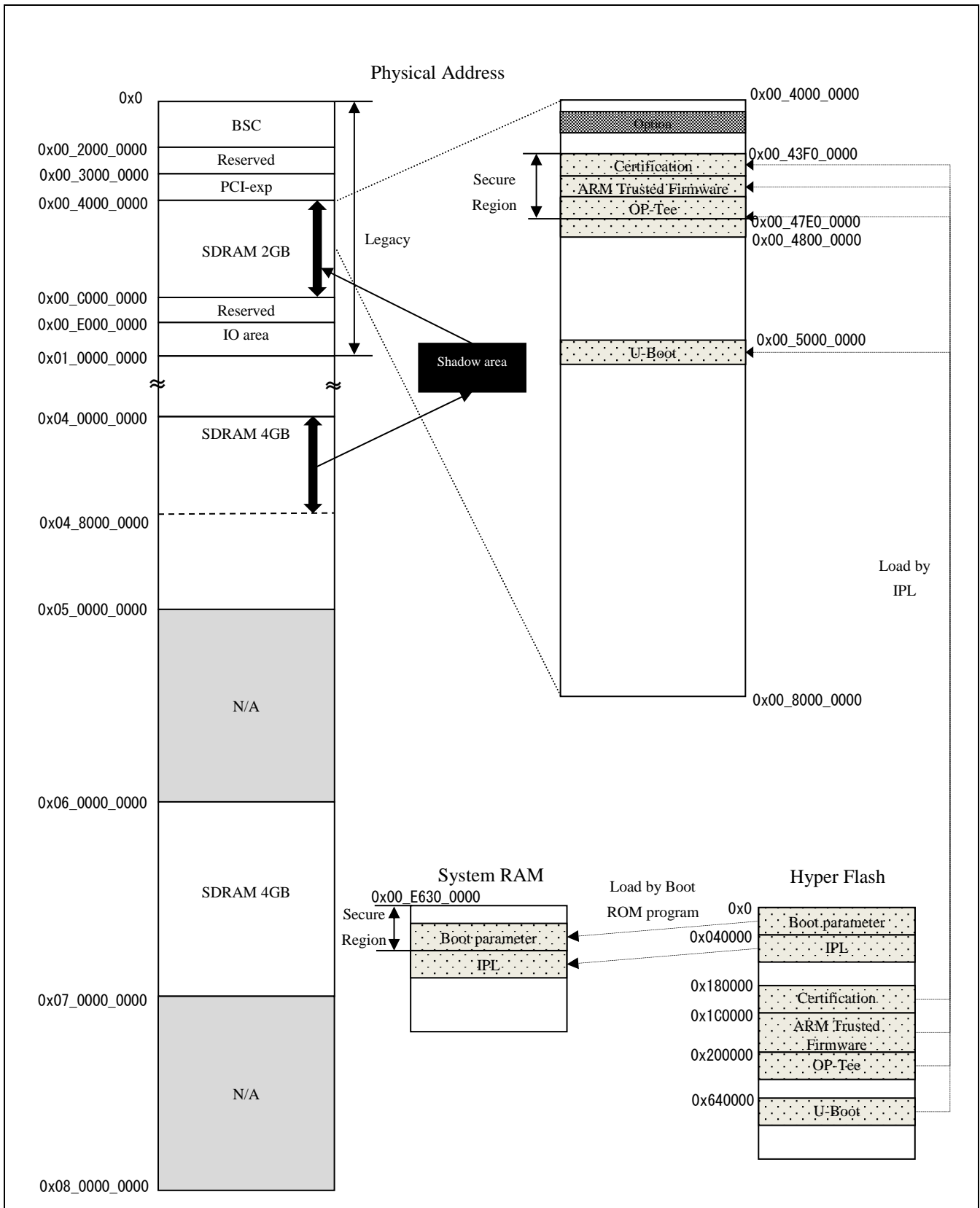


Figure 6. M3 Ver.3.0 8GB memory map (Boot)

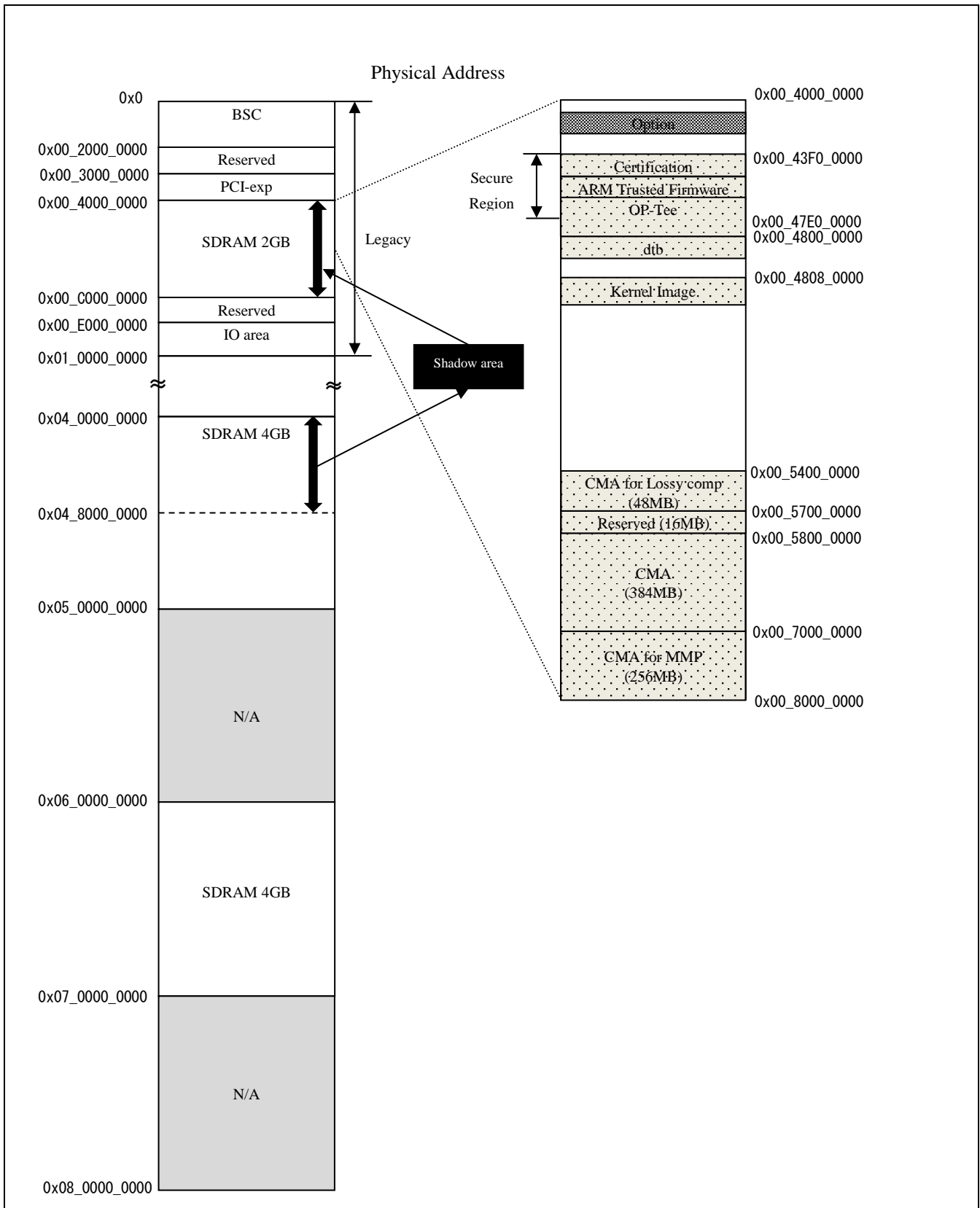


Figure 7. M3 Ver.3.0 8GB memory map (Linux)

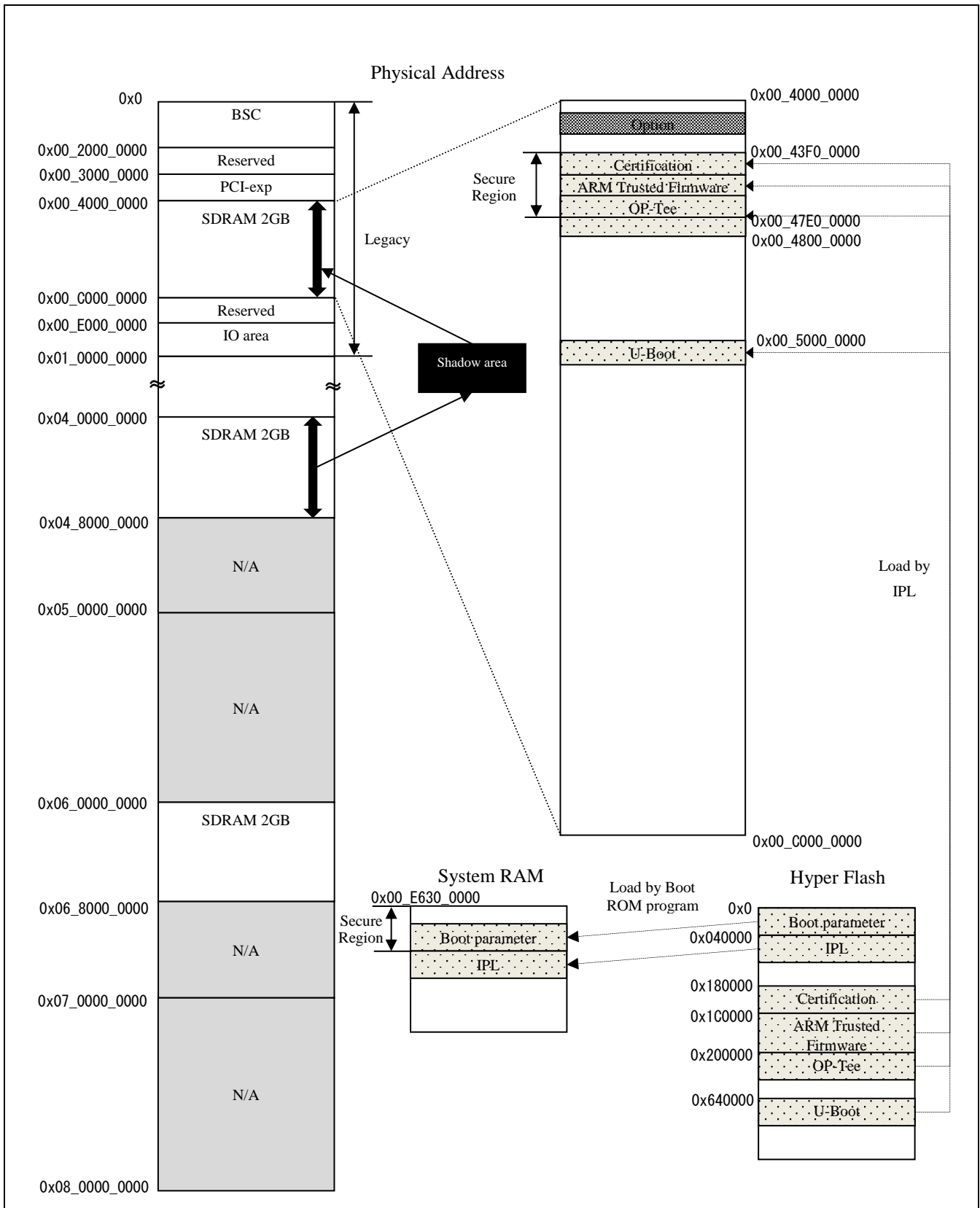


Figure 8. M3 Ver.1.x (4GB) memory map (Boot)

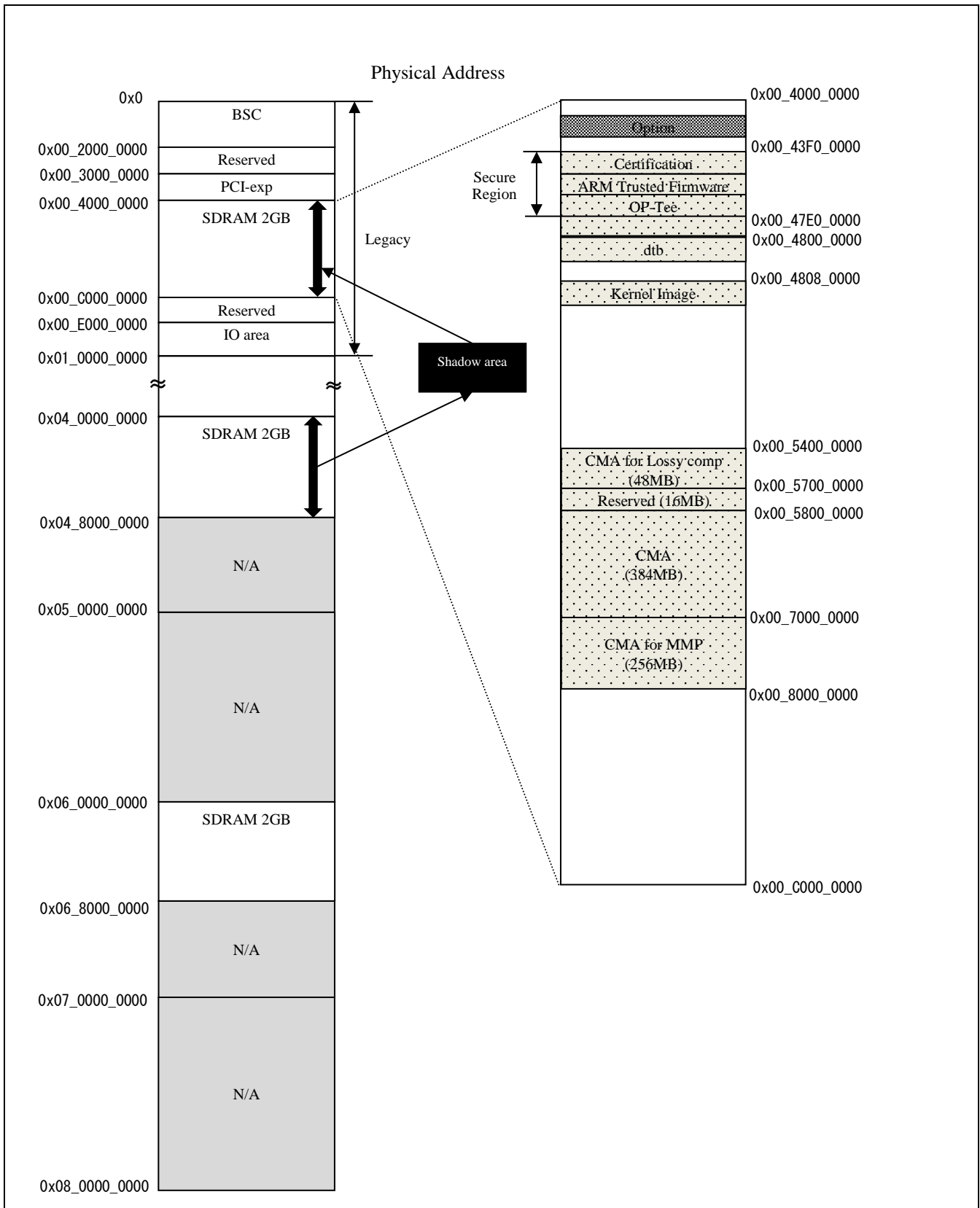


Figure 9. M3 Ver.1.x (4GB) memory map (Linux)

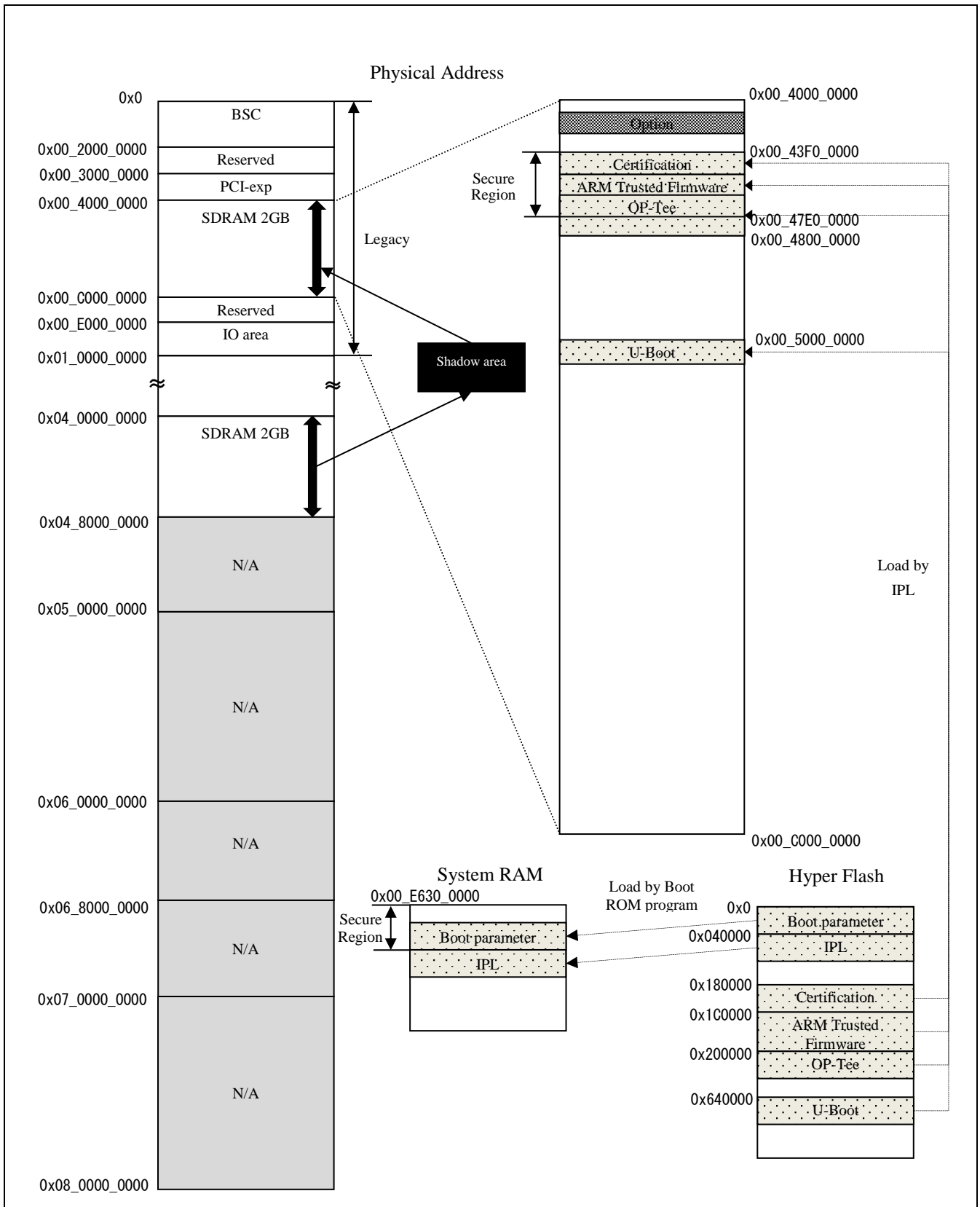


Figure 10. M3N memory map (Boot)

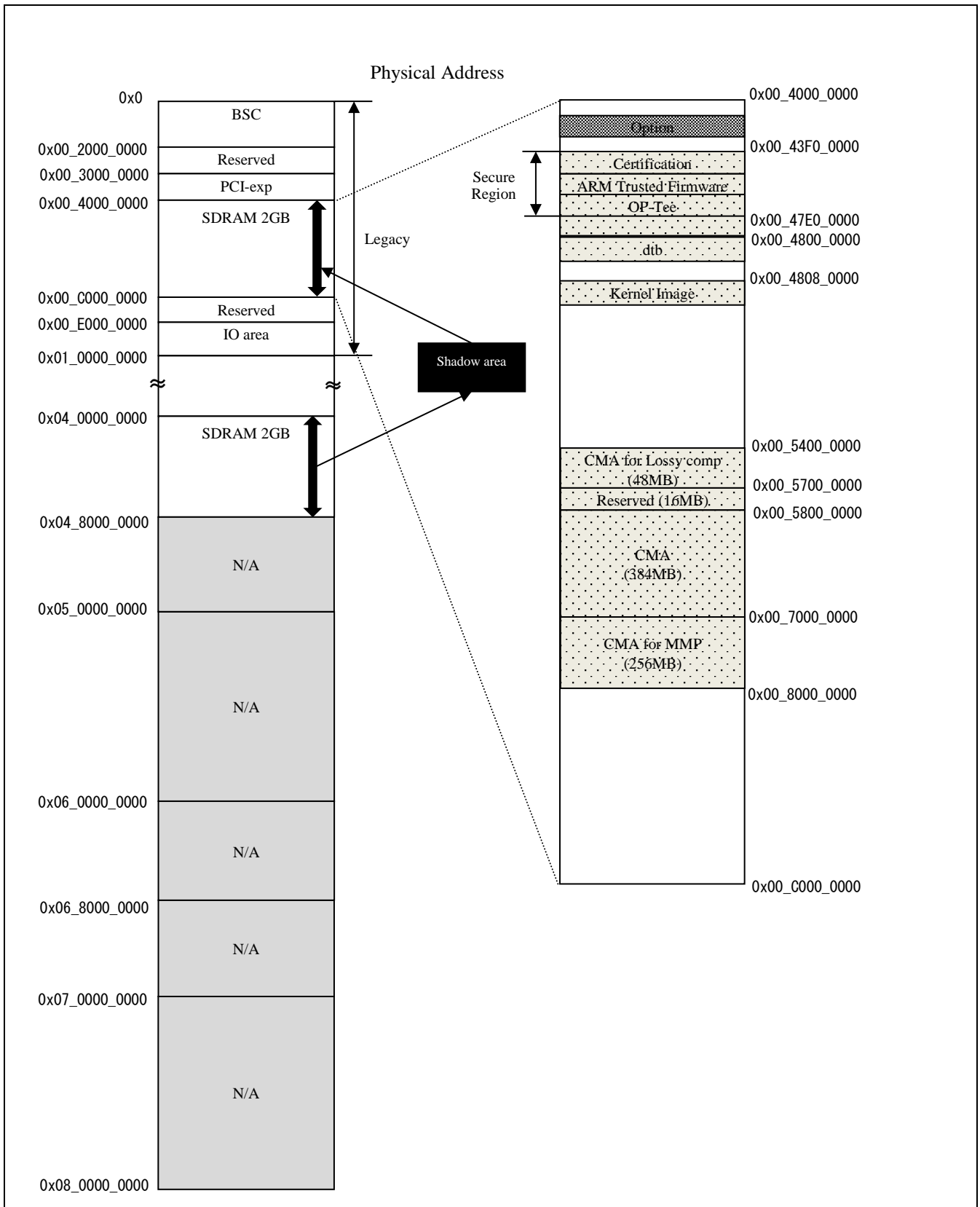


Figure 11. M3N memory map (Linux)

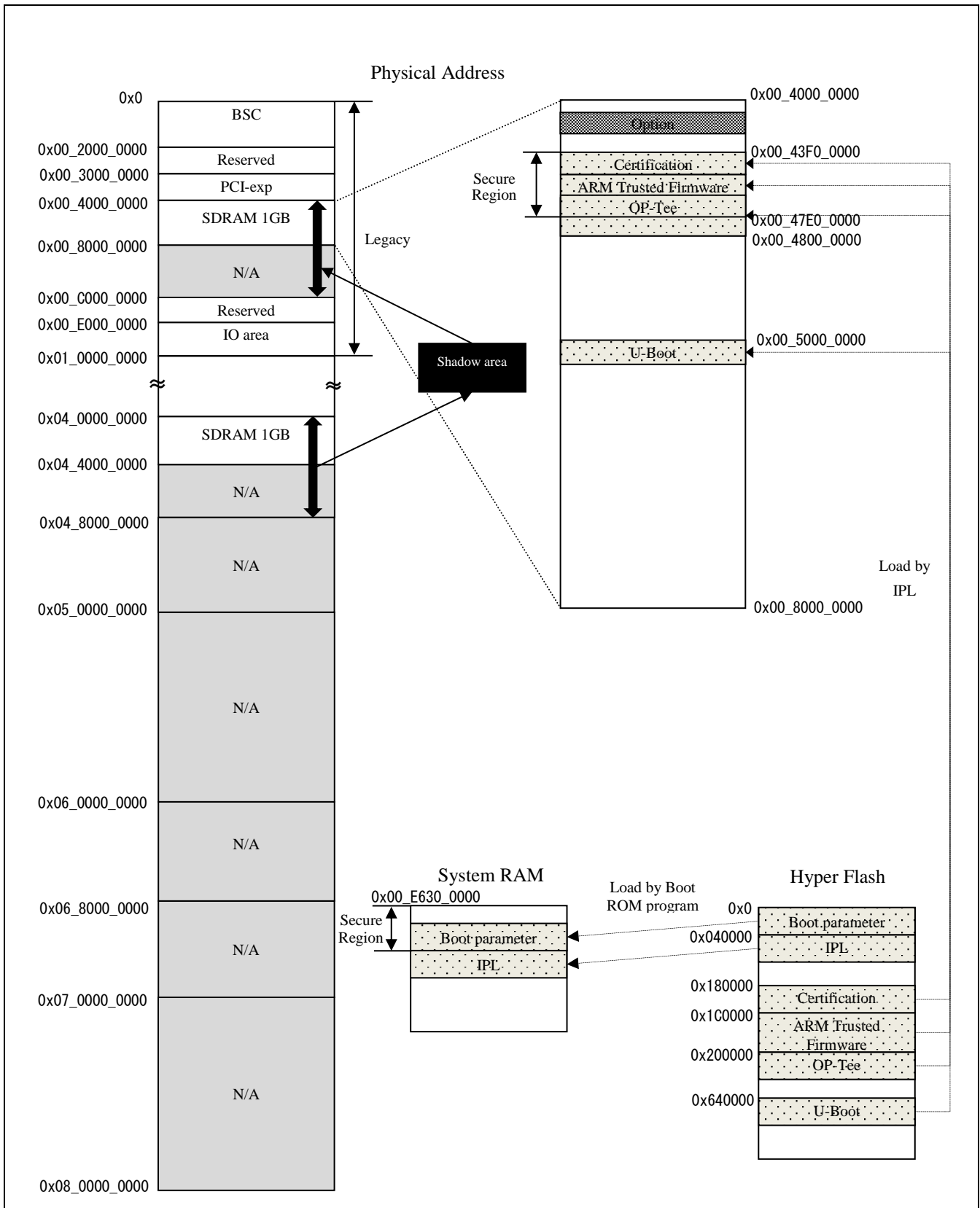


Figure 12. E3 System Evaluation Board Ebisu memory map (Boot)

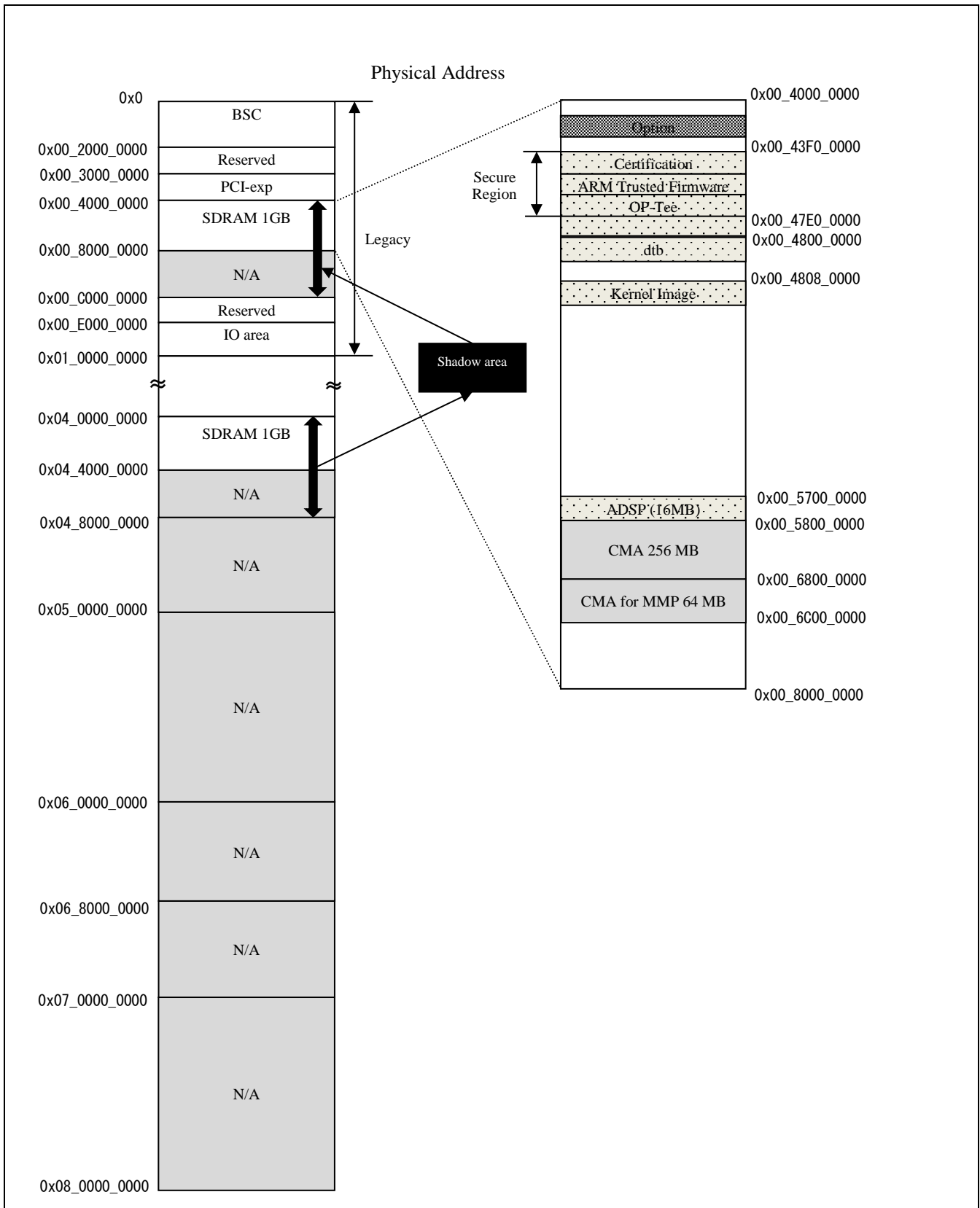


Figure 13. E3 System Evaluation Board Ebisu memory map (Linux)

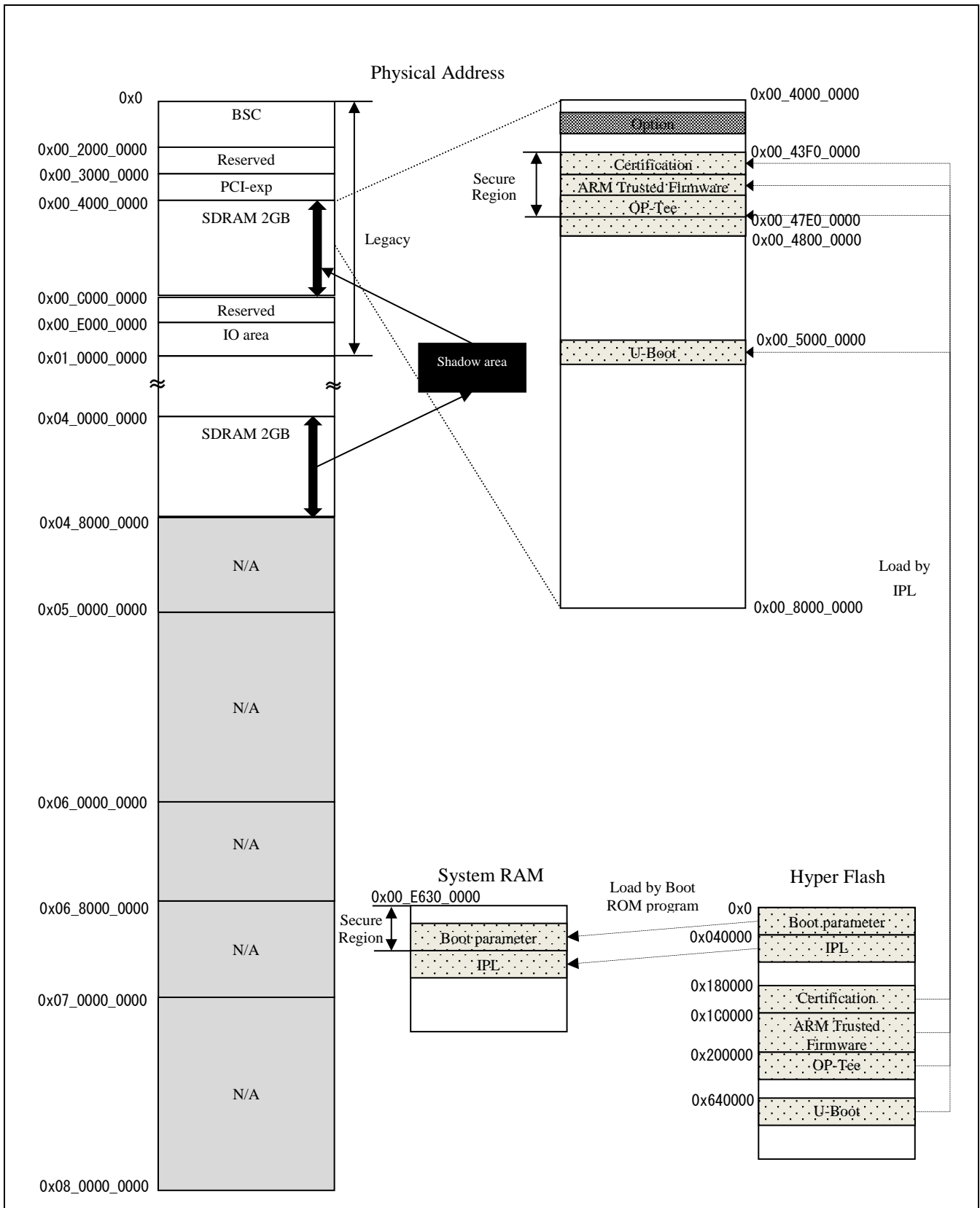


Figure 14. E3 System Evaluation Board Ebisu-4D memory map (Boot)

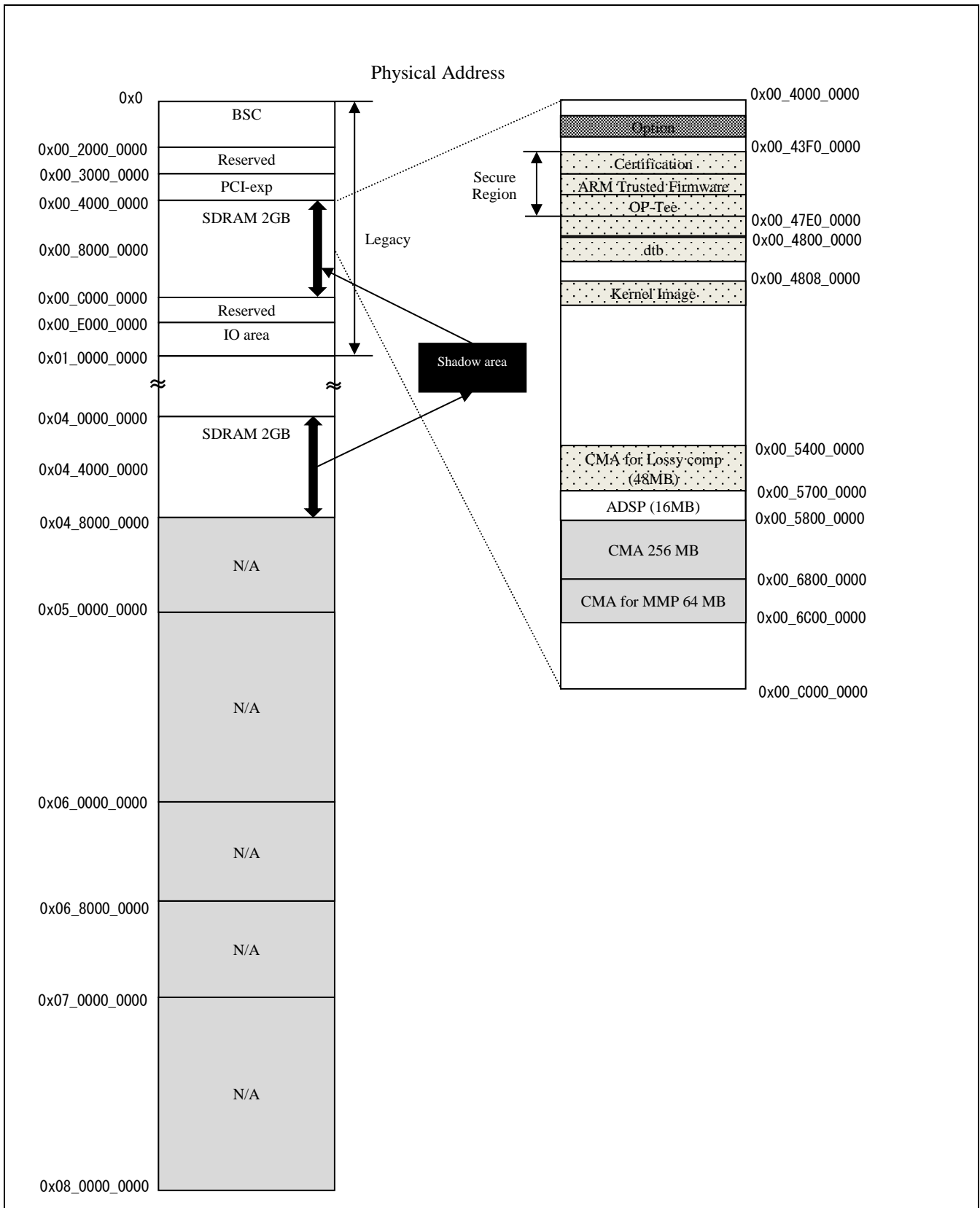


Figure 15. E3 System Evaluation Board Ebisu-4D memory map (Linux)

Note)

- Kernel region is assigned by Kernel device tree arch/arm64/boot/dts/renesas/xxx.dts and totally mapped to 8GB (R-Car H3 Ver.3.0 8GB, R-Car M3 Ver.3.0), 4GB (R-Car H3 Ver.3.0 4GB/Ver.2.0/M3 Ver.1.x), 2GB (R-Car M3N), 1GB (R-Car E3 System Evaluation Board Ebisu) and 2GB (R-Car E3 System Evaluation Board Ebisu-4D).
- Kernel region consists of 4 parts: (R-Car H3 Ver.3.0 8GB)
 - 1920MB from 0x00_4800_0000 to 0x00_BFFF_FFFF
 - 2GB from 0x05_0000_0000 to 0x05_7FFF_FFFF
 - 2GB from 0x06_0000_0000 to 0x06_7FFF_FFFF
 - 2GB from 0x07_0000_0000 to 0x07_7FFF_FFFF
- Kernel region consists of 4 parts: (R-Car H3 Ver.3.0 4GB/Ver.2.0)
 - 896MB from 0x00_4800_0000 to 0x00_7FFF_FFFF
 - 1GB from 0x05_0000_0000 to 0x05_3FFF_FFFF
 - 1GB from 0x06_0000_0000 to 0x06_3FFF_FFFF
 - 1GB from 0x07_0000_0000 to 0x07_3FFF_FFFF
- Kernel region consists of 2 parts: (R-Car M3 Ver.1.x)
 - 1920MB from 0x00_4800_0000 to 0x00_BFFF_FFFF
 - 2GB from 0x06_0000_0000 to 0x06_7FFF_FFFF
- Kernel region consists of 3 parts: (R-Car M3 Ver.3.0)
 - 1920MB from 0x00_4800_0000 to 0x00_BFFF_FFFF
 - 2GB from 0x04_80000_0000 to 0x04_FFFF_FFFF
 - 4GB from 0x06_0000_0000 to 0x06_FFFF_FFFF
- Kernel region consists of 1 part: (R-Car M3N)
 - 1920MB from 0x00_4800_0000 to 0x00_BFFF_FFFF
- Kernel region consists of 1 part: (R-Car E3 System Evaluation Board Ebisu)
 - 896MB from 0x00_4800_0000 to 0x00_7FFF_FFFF
- Kernel region consists of 1 part: (R-Car E3 System Evaluation Board Ebisu-4D)
 - 1920MB from 0x00_4800_0000 to 0x00_BFFF_FFFF

There are three types of CMA regions.

They are defined in device tree (arch/arm64/boot/dts/renesas/xxxx.dts).

- Default CMA region: It is for kernel, general drivers and multimedia package.

```
linux,cma {
    compatible = "shared-dma-pool";
    reusable;
    reg = <0x00000000 0xFFFFFFFF 0x0 0xFFFFFFFF>;
    linux,cma-default;
};
```

0xFFFFFFFF is start address of CMA region.
0xFFFFFFFF is size of CMA region.

Note)

- 128 MB in this CMA (H3/M3/M3N 384MB, E3 256MB) is reserved for kernel and general drivers, and the remaining H3/M3/M3N 256 MB, E3 128MB is reserved for multimedia package.
- The CMA region can be adjusted by changing the start address and the size.
- Should take care of the lack of memory allocated by kernel and general drivers when reducing the region size.

- CMA region for MMP: It is for multimedia package (specific H/Ws).

```
mmp_reserved: linux,multimedia {
    compatible = "shared-dma-pool";
    reusable;
    reg = <0x00000000 0xFFFFFFFF 0x0 0xFFFFFFFF>;
};
```

0xFFFFFFFF is start address of CMA region.
0xFFFFFFFF is size of CMA region.

Note)

- Refer to User's manual of Memory Manager in order to change CMA region for MMP.

- H3/M3/M3N CMA region for Lossy comp: It is for storing data compressed by Frame Compression Near Lossless (FCNL) for media playback.

```
lossy_decompress: linux,lossy_decompress {
    no-map;
    reg = <0x00000000 0xFFFFFFFF 0x0 0xFFFFFFFF>;
};
```

0xFFFFFFFF is start address of CMA region.
0xFFFFFFFF is size of CMA region.

Note)

- Refer to User's manual of IPL in order to change CMA region for Lossy comp.

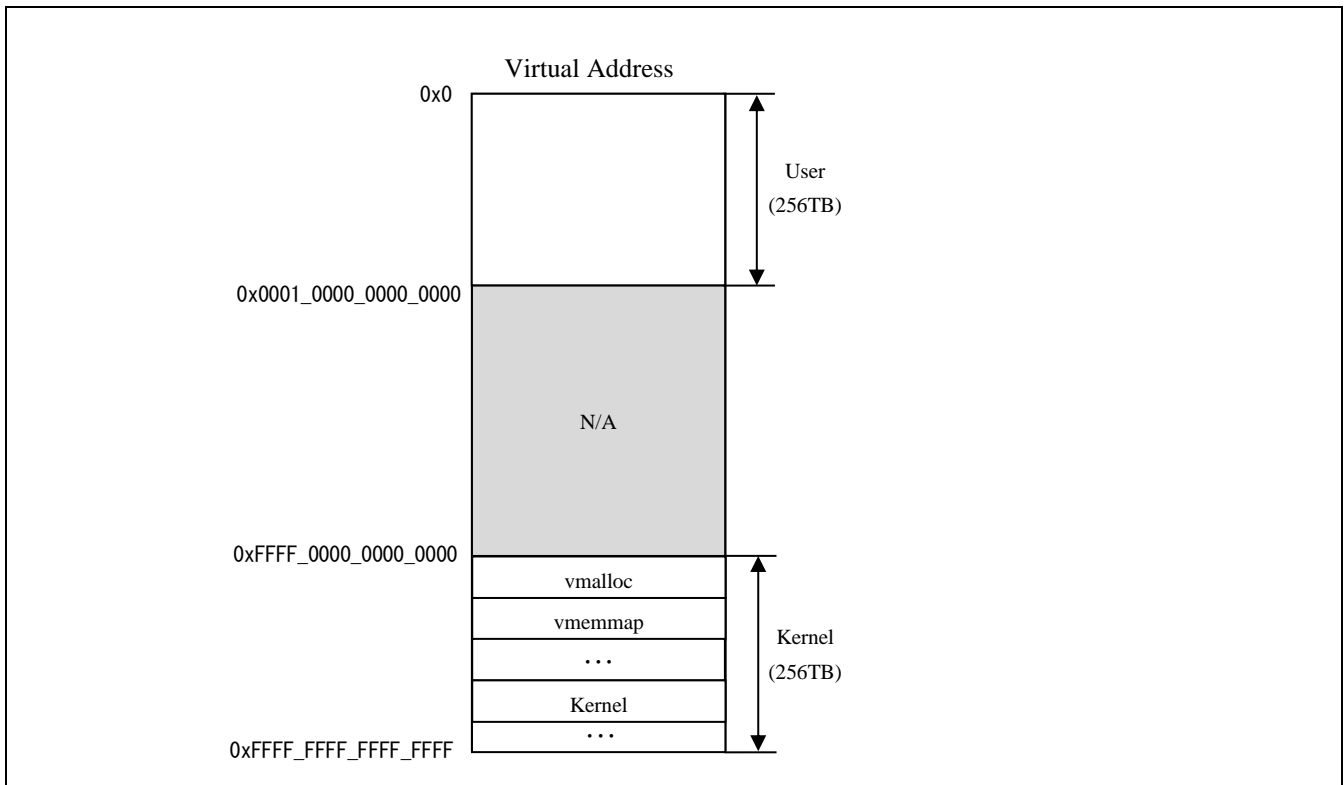


Figure 16. H3/M3/M3N/E3 memory map (Virtual)

Note)

- Kernel uses 4KB page size (VA_BITS=48) and 4 levels of translation tables. Both regions of User and Kernel are 256TB. Refer to Documentation/arm64/memory.txt.
- Detail information about kernel memory map in virtual address space, refer to User's manual of Kernel.

8. U-Boot command

Please refer to U-Boot user's manual about available U-Boot command for R-Car H3/M3/M3N/E3 Linux BSP. The help or “?” command shows U-Boot command list, but be careful that it includes some unsupported command.

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REVISION HISTORY		Linux Interface Specification Yocto recipe Start-Up Guide User's Manual: Software	
Rev.	Date	Description	
		Page	Summary
0.10	Sep 07. 2015	—	First Edition for Yocto Recipe Package with YP1.8, based on Start-Up Guide Rev 1.30 for Kernel 3.4 LTSI
0.20	Sep 30. 2015	2	1 Modified URL of U-Boot and Linux source code.
		6	3 Deleted description about core-image-x11
		6	3 step2 Changed git repository URL
		9	3.2 Added note about not support 3D graphics package 3.2 step5,7 Changed command process
		12	4.1 Changed U-Boot filename. u-boot.srec -> u-boot-elf.srec
		21, 22	7 Modified memory map (Fig2, 3)
0.30	Oct 30 2015	2	1.1 Modified document version
		3	2.1 Updated table1
		4	2.1 Updated Figure1
		7	3 Modified checkout commit id 3 step4 Updated apply patch command
		8-12	3.1 Added description build procedure for MMP and 3D Graphics
		14	4.4 Deleted note
		18	5 step6 Added mem=2048 to bootargs 5 step8 Added note
		19-21	6 Modified SDK revision 1.8 -> 1.8.1
		22	7 Modified the description of the address range. 0x00_C000_0000 -> 0x00_BFFF_FFFF 7 Modified the address range and size of a secure region.
		23	7 Modified the address of System RAM. 0x00_E630_0000 -> 0x00_E632_0000 7 Modified the load destination of Certification in HyperFlash. System RAM -> SDRAM
		24, 25	7 Modified memory map (Fig3) and update note about CMA 7 Added note about specifying mem=2048M 7 Added note about 3D graphics region
0.40	Nov 27 2015	26	7 Separated virtual memory map (Fig4) and note about virtual memory
		7	3 Modified checkout commit id 3 step4 Updated apply patch command
0.50	Dec 25 2015	18	5 step6 Added note about adding consoleblank=0 in bootargs 5 step7 Added description saveenv command 5 step9 Modified start Linux procedure
		6	3 step1 added python-crypto 3 step2 added meta-openembedded
		7	3 Modified checkout commit id
		17	5 step5 deleted note
0.61	Jan 25 2016	18	5 step9 added USB channel number
		7	3 Modified checkout commit id 3 step4 Changed patch command
		10	3.1 step10 Fixed typo in captor name

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			3.1 step10 Deleted note for mem=2048M in bootargs
		12	3.2 step9 Deleted note for mem=2048M in bootargs
		14	4.1 Changed Hex notation. 0XXXXX -> H'XXXX
		18	5 step6 Deleted mem=2048M in bootargs 5 step9 Add note about XDG_RUNTIME_DIR
		19-21	Changed SDK version to 2.0 from 1.8.1
		20	6 step3 Add note about overwrite installation
0.70	Feb 25 2016	2	1.1 Modified document version
		7	3 Modified checkout commit id
		8	3.1 step5 Renewed description
		11	3.2 step5 Renewed description
		18	5 step8 Deleted console setting from bootargs 5 step9 Add note about writing MAC address
		19-21	Changed SDK version to 2.0.1 from 2.0
0.80	Mar 25 2016	5,6	2.2 Add R-Car H3 Ver.1.1 and changed setting value of SW11-4pin in Ver.1.0
		8	3 Modified checkout commit id
		10,11	3.1 step9 Add Type name of MMP and dependence package list
		18	5 Deleted note
		25	7 Modified memory map (Fig3) and remove the 3D Graphics specific region
		26	Deleted the description of "mem=" and update Kernel region
0.90	Apr 25 2016	all	Added description for R-Car M3. For example, R-Car H3 -> R-Car H3/M3
		2	1.1 Modified document version 1.1 Deleted "R-Car Series, 3 rd Generation Electorical Characteristics"
		6	2.2 Add table4 for R-Car M3
		8	3 Modified checkout commit id
		9	3.1 Added note for R-Car M3
		11-12	3.1 step9 Updated Multi Media Package list
		13	3.1 step10 Added select SoC
		15	3.2 step9 Added select SoC
		16	3.3 step7 Added select SoC
		21	5 step5 Changed description setenv command, and added note for SOC_FAMILY
		27,28	Modified memory map(Fig2 and Fig3) of H3
		29,30	Added memory map(Fig4 and Fig5) of M3
		31	Added description of M3 kernel region
		32	Added description of CMA region for Lossy comp
2.9.0	May 25 2016	-	Changed Revision number rule. Document revision number is Yocto Recipe version.
		6	2.2 Modify table4. RCar M3: DDR1600 -> DDR3200
		8	3 Modified checkout commit id
		9	3.1 deleted note for R-Car M3
		11-12	3.1 step9 Fix TYPO and added aacPlus V2 decoder, ADSP, Ether-AVB
2.10.0	Jun 27 2016	2	1 Updated linux source code URL
		8	3 Modified checkout commit id
		19	4 step3 added message for SW31 in R-Car M3
		23-25	6 Changed version of SDK. 2.0.1 -> 2.0.2
		26	Added note of "CMA for Lossy comp" region

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		26,27, 29	Added description of 8KB Secure region from 0xE6300000 Modified memory map(Fig2 and Fig4) of H3/M3
		32	Changed virtual address space from 39-bit to 48-bit Modified memory map(Fig 6)
2.11.0	Jul 25 2016	2	1.1 Modified Reference
		8	3 Modified checkout commit id
		10	3 step9 Updated standard multimedia package table
		11-14	3 step9 Updated optional multimedia package table
		20	4.2 Updated Dip-Switch setting for R-Car H3 Ver.1.1 and M3 Ver.1.0
		23	5 Added description about refer to Dip-Switch setting
		24	5 step9 Modified note for USB connector. R-Car M3 support only CN10 of USB2_2
		23-24	5 Deleted description of 32bit environment
		25-26	6 Deleted description of 32bit SDK
		33	7 Updated device tree source code of CMA region for Lossy comp
2.12.0	Aug 25 2016	2	1 Updated linux source code URL
		2	1.1 Modified Reference
		3	2.1 Updated table 1
		5	2.2 Updated table 2
		7	3 step1 Added note about git config
		8	3 step3 Modified checkout commit id
		11-14	3 step9 Updated optional multimedia package table
		25	6 Updated note about environment variables
		25-26	6 Deleted description of 32bit SDK
2.15.0	Dec 07, 2016	5	2.2 Added note for setting of dip switch
		6	Table4 Added "**1" for SW11-pin4.
		8	3 Modified checkout commit id
		11-14	Fixed Type name of Dolby(R) Digital decoder middleware library
		20	4.1 Changed U-Boot Program Top Address
		23	5 Step 4 Changed U-Boot Program Top Address
		23-24	5 Step 5 Changed dtb filename. Added notes about R-Car H3 device trees names.
		27	6 Step 2,3,4 Updated Yocto Project version to 2.1.2
		28-34	7 Updated Memory map corresponding to new BSP v3.4.0
2.16.0	Jan 27, 2017	8	3 Modified checkout commit id
		10	3 step9 Updated to use H263 Dec as example
		11-14	3 step9 Updated optional multimedia package table to add H263 Dec
		13	3 step9 Changed description "Independence package" to "Dependent package"
		25	5 step9 Changed XDG_RUNTIME_DIR value to XDG_RUNTIME_DIR=/run/user/0
		26	6 step1 Fixed typo: SDK_MACHINE -> SDKMACHINE
2.17.0	Mar 30, 2017	-	Changed description of variables from \$foo to \${foo}
		2	1.1 Updated related documents. Added R-CarH3-SiP/M3-SiP System Evaluation Board Salvator-XS Hardware Manual
		5	2.2 Added Setting of Dip switches for R-Car H3 Ver.2.0 (Salvator-X/XS board)
		8	3 Modified checkout commit id
		20	4.1 Change address format from H'xxxx to 0xxxxx

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			Changed bl2-<board_name>.srec Program Top Address.
		24	Deleted notes about R-Car H3 device trees names.
		25	5 step9 Corrected USB port of M3. Deleted note about setting XDG_RUNTIME_DIR.
		28	7 Expanded secure regions in System RAM.
		33	7 Clarified the use of the default CMA region.
2.19.0	Apr 26, 2017	-	Unified the Chip version "Ver/ES/WS" to "Ver."
		-	Changed "U-boot" to "U-Boot".
		5-6	2.2 Updated Setting of Dip switches for R-Car M3 Ver.1.1 (Salvator-X/XS board)
		8	3 Modified checkout commit id.
		16	Changed description of variables from \$PKGS_DIR to \${PKGS_DIR}.
		24	Updated notes about R-Car M3 device trees names.
2.21.0	Jun 28, 2017	2	1.1 Modified document version
		8	3 Modified checkout commit id.
2.23.0	Aug 29, 2017	-	Add "CONFIDENTIAL" mark
		8	3 Modified checkout commit id.
2.23.1	Nov 28, 2017	-	Added description for R-Car M3N.
		2	1.1 Modified document version.
		5	2.2 Table 2 added SW31 description.
		8	Step 3 Update Poky version to 2.1.3
		15-18	Added R-Car M3N SOC_FAMILY.
		24	Added "r8a77965" for SOC_FAMILY. Added R-Car M3N device trees information.
		27	Update Poky version to 2.1.3.
		28	7 Added the volume of SDRAM information of R-Car M3N.
		33-34	7 Added memory maps of R-Car M3N.
3.2.0	Nov 28, 2017	—	First Edition for Yocto Recipe Package with YP2.4, based on Start-Up Guide Rev 2.23.1 for Kernel 4.9 LTSI
3.4.0	Jan 29, 2018	2	1.1 Modified document version
		3	2.1 Add Ubuntu/Windows and Tera Term version requirement
		8	3 Modified checkout commit id.
		11-14	Step 8 Updated Multimedia package names
		24	Step 6 Added a new note for disabling big.LITTLE architecture in R-Car H3/M3
		27	Modified Toolchains version
3.6.0	Mar 28, 2018	-	Added description for R-Car E3
		2	1.1 Add E3 document reference
		10	3 Modified checkout commit id
		27	6 Add instruction to use toolchain in case of 'make menuconfig'
		36-37	7 Add memory maps of R-Car E3
3.7.0	Apr 25, 2018	6	Delete setting of Dip switches (R-Car H3 Ver.1.0) and (R-Car H3 Ver.1.1) and (R-Car M3 Ver.1.0)
		9	3 Modified checkout commit id
		16-19	3 Add notes about selecting U-boot/IPL option for H3
		25	5 Add name of device trees of R-Car H3 Ver.3.0
		28	6 Changed SDK version to 2.4.2 from 2.4.1

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		29-42	7 Add memory maps of R-Car H3 Ver.3.0 and update memory map of R-Car E3
3.9.0	Jun 27, 2018	9	3 Modified checkout commit ID
		5	2.2 Added M3 Ver.1.2
		25	5 Added M3 Ver.1.2
3.9.0.1	Oct 22, 2018	2	1.1 Updated reference document version
		9	3 Modified checkout commit ID
		16, 18, 19	3.1, 3.2, 3.3 Made clear Ebisu SoC selection. No need to modify SOC_FAMILY for Ebisu
		25	5 Removed system halt issue when screen saver starts.
		10, 11, 17	3 Used Markdown format (.md) for README files
3.13.0	Oct 29, 2018	2	1.1 Added Evaluation Board Hardware Manual reference for R-Car E3 System Evaluation Board Ebisu-4D.
		7	Table 3 Added R-Car E3 System Evaluation Board Ebisu-4D.
		9	3 Modified checkout commit ID.
		16,18, 19	Step 9/8/6 select SoC Removed H3_OPTION note.
		21	4.1 Changed file names of U-boot/IPL. Added note for extension.
		24	Step 4 Changed u-boot file name.
		25	Step 5 Added the device trees name of R-Car E3 System Evaluation Board Ebisu-4D.
		28	Modified Toolchains version.
		29	7. Added SoC version. Added R-Car E3 System Evaluation Board E3-4D information.
		38, 39	7. Modified memory map name (Fig10 and Fig11) of R-Car E3 System Evaluation Board Ebisu.
		40, 41	7. Added memory map (Fig12 and Fig13) of R-Car E3 System Evaluation Board Ebisu-4D.
3.15.0	Dec 25, 2018	42	Added R-Car E3 System Evaluation Board Ebisu-4D information.
		2	1.1 Updated reference document name and version
		9	3 Modified checkout commit ID
		21	4.1 Changed file names of U-boot/IPL. Added note for extension.
		23	Step 3 Updated Mini-Monitor message of new version and added E3 Ebisu board's SW31 Mini-Monitor message
		25	Step 4 Changed u-boot file name.
3.19.0	Apr 17, 2019	26	Step 5 Updated the device trees name of R-Car E3
		2	1.1 Updated reference document name and version
		6	Table 2 Updated information for M3 Ver.1.3
		9	3 Modified checkout commit ID
3.21.0	Jul 26, 2019	26	Step 5 Update device trees for M3 Ver.1.3
		6	Table 2: Added M3 Ver.3.0
		9	3 Modified checkout commit ID
		21	4.1 Added U-Boot/IPL table for M3 Ver.3.0
		26	5 Added U-Boot file for M3 Ver.3.0
		27	5 Added device tree file for M3 Ver.3.0
		29	6 Used direct version number for toolchain manual link
		31	7 Added M3 Ver.3.0 information
		36-37	7 Added M3 Ver.3.0 memory map

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		46	Added Kernel region memory for M3 Ver.3.0
4.1.0	June 30, 2020	2	1 Update Kernel repository URL
		8	Step 1 Updated installation of required commands Step 2 Removed meta-linaro
		9	3 Modified checkout commit ID
		26, 27	Step 5 Removed "Image" prefix
		29, 30	6 Change SDK version to 3.0.2 from 2.4.3

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Linux Interface Specification Yocto recipe Start-Up Guide
User's Manual: Software

Publication Date: **June. 30, 2020** **Rev.4.1.0**

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Renesas Electronics Corporation

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan

Renesas Electronics America Inc. Milpitas Campus

1001 Murphy Ranch Road, Milpitas, CA 95035, U.S.A.
Tel: +1-408-432-8888, Fax: +1-408-434-5351

Renesas Electronics America Inc. San Jose Campus

6024 Silver Creek Valley Road, San Jose, CA 95138, USA
Tel: +1-408-284-8200, Fax: +1-408-284-2775

Renesas Electronics Canada Limited

9251 Yonge Street, Suite 8309 Richmond Hill, Ontario Canada L4C 9T3
Tel: +1-905-237-2004

Renesas Electronics Europe GmbH

Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-211-6503-0, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.

Room 101-T01, Floor 1, Building 7, Yard No. 7, 8th Street, Shangdi, Haidian District, Beijing 100085, China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.

Unit 301, Tower A, Central Towers, 555 Langao Road, Putuo District, Shanghai 200333, China
Tel: +86-21-2226-0888, Fax: +86-21-2226-0999

Renesas Electronics Hong Kong Limited

Unit 1601-1611, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2265-6688, Fax: +852 2886-9022

Renesas Electronics Taiwan Co., Ltd.

13F, No. 363, Fu Shing North Road, Taipei 10543, Taiwan
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.

80 Bendemeer Road, #06-02 Singapore 339949
Tel: +65-6213-0200, Fax: +65-6213-0300

Renesas Electronics Malaysia Sdn.Bhd.

Unit No 3A-1 Level 3A Tower 8 UOA Business Park, No 1 Jalan Pengaturcara U1/51A, Seksyen U1, 40150 Shah Alam, Selangor, Malaysia
Tel: +60-3-5022-1288, Fax: +60-3-5022-1290

Renesas Electronics India Pvt. Ltd.

No.777C, 100 Feet Road, HAL 2nd Stage, Indiranagar, Bangalore 560 038, India
Tel: +91-80-67208700

Renesas Electronics Korea Co., Ltd.

17F, KAMCO Yangjae Tower, 262, Gangnam-daero, Gangnam-gu, Seoul, 06265 Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5338



ルネサスエレクトロニクス株式会社

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<http://www.renesas.com>

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ルネサス エレクトロニクス株式会社 〒135-0061 東京都江東区豊洲3-2-24（豊洲フォレシア）

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